

Fig. 1A

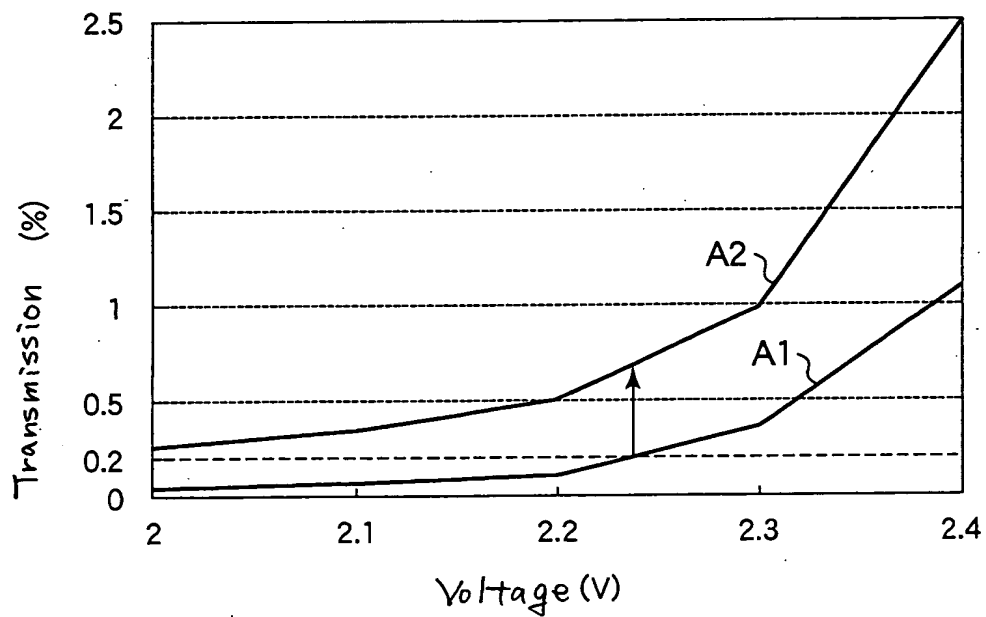


Fig. 1B

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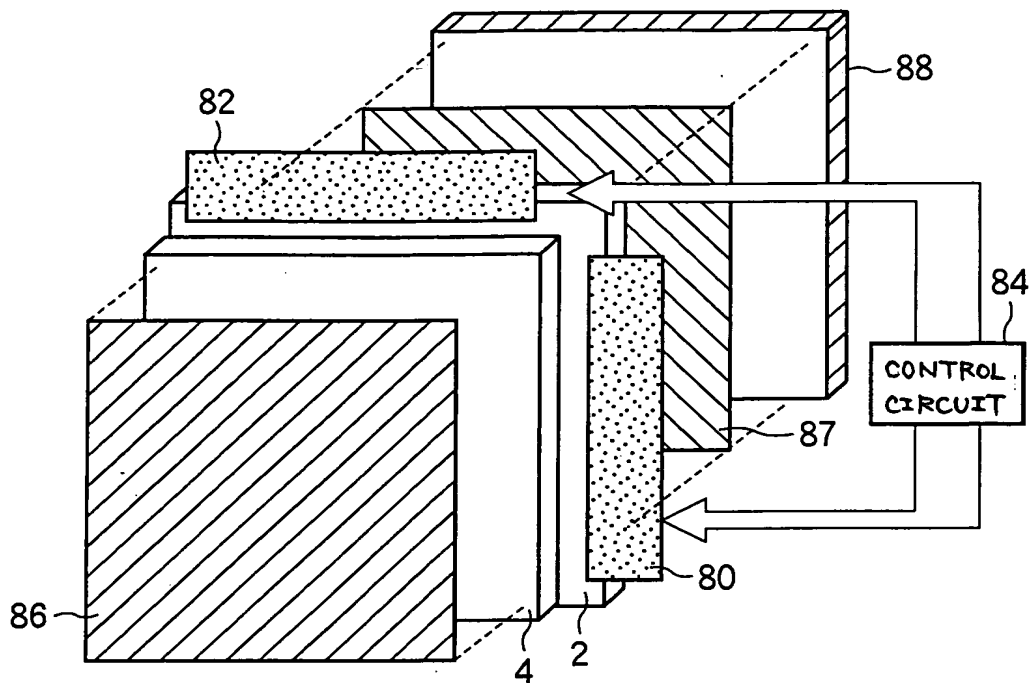


Fig. 2

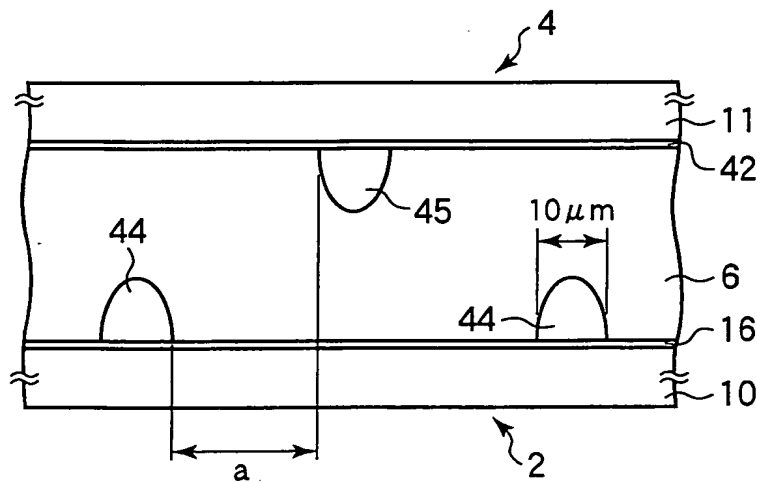


Fig. 3

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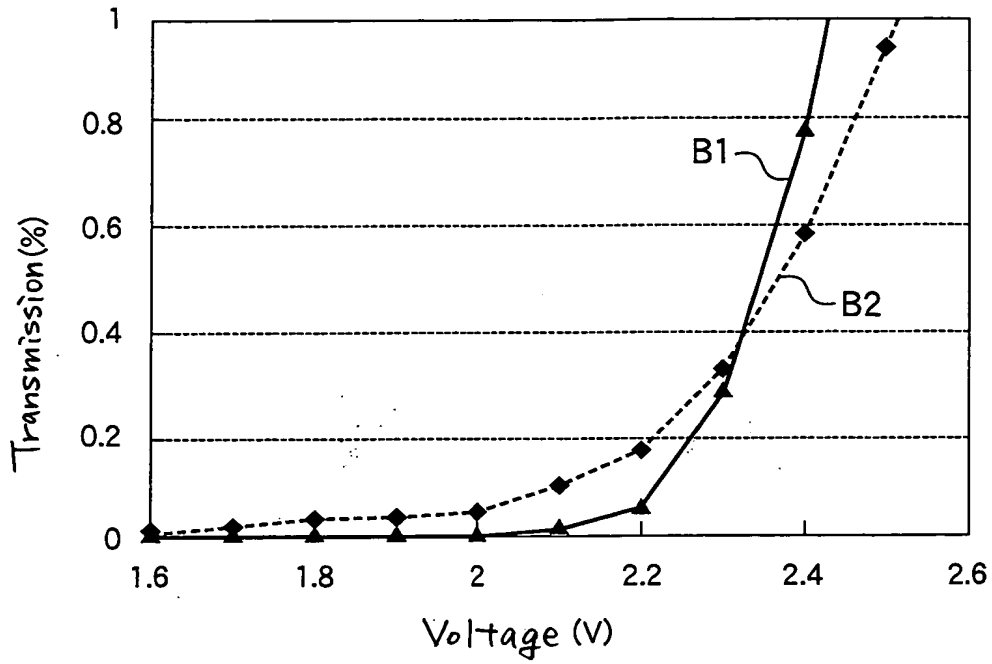


Fig. 4

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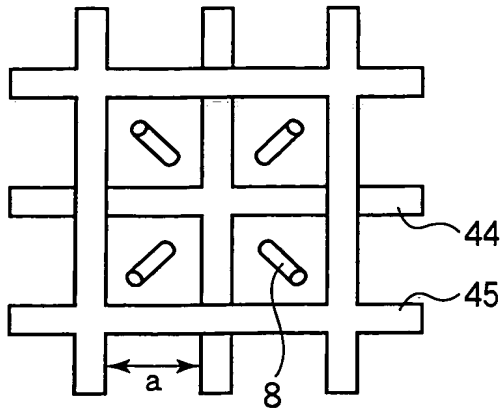


Fig. 5A

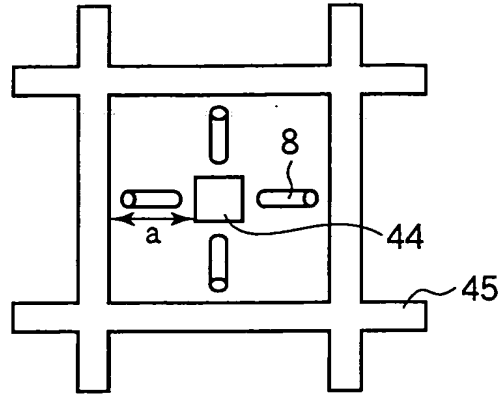


Fig. 5B

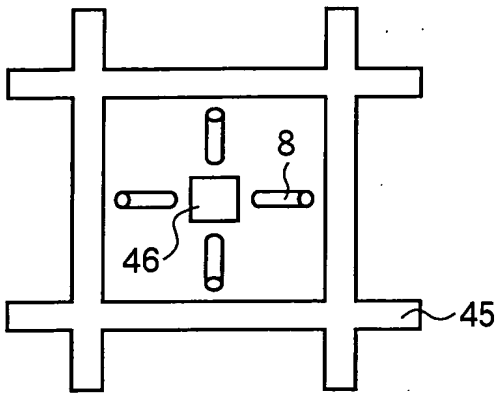


Fig. 5C

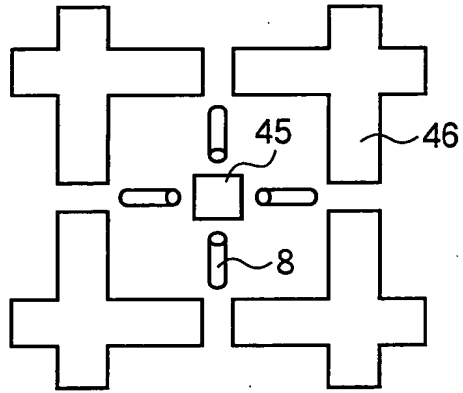


Fig. 5D

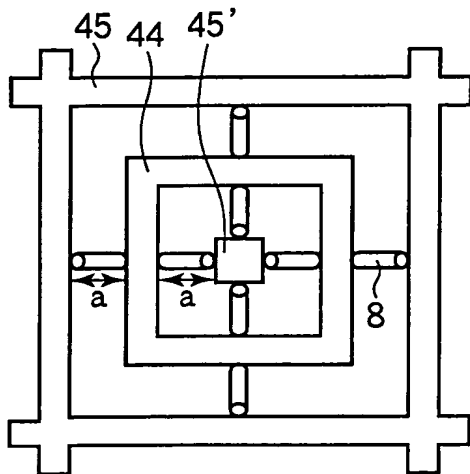


Fig. 5E

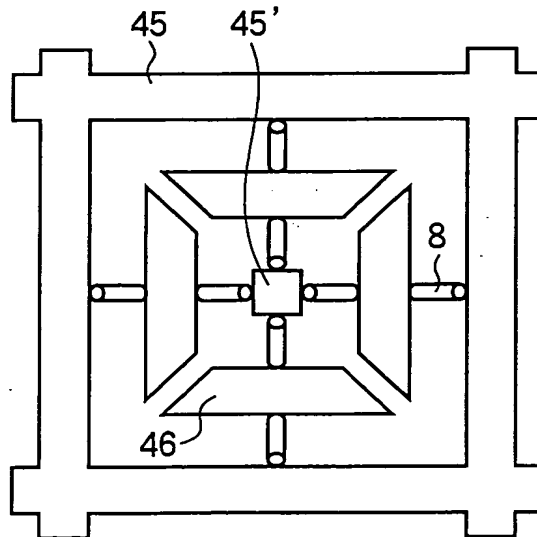
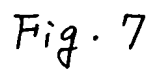
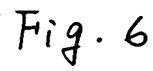


Fig. 5F



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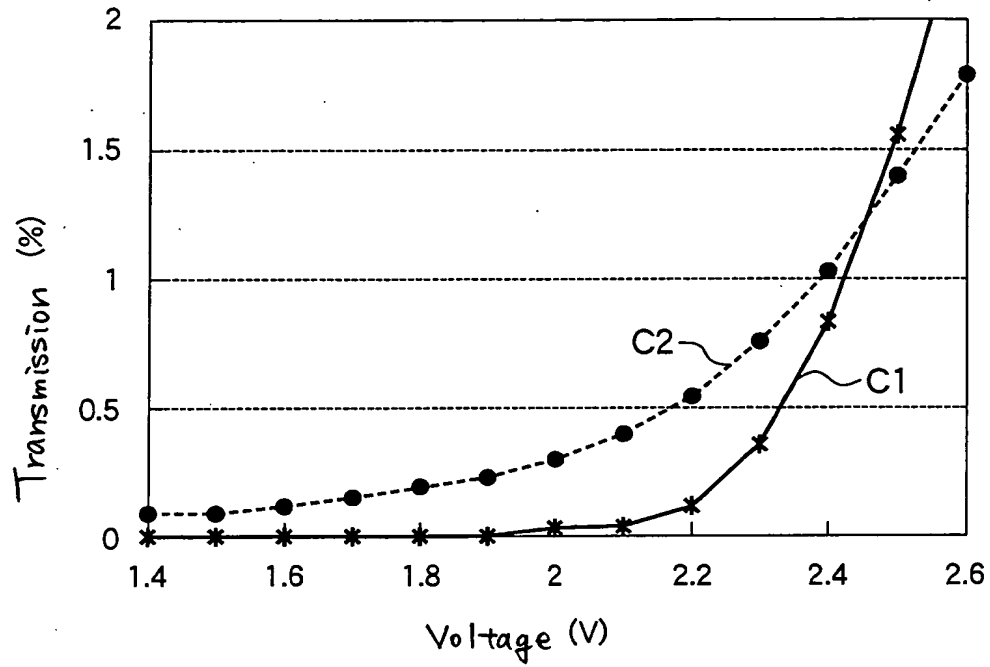


Fig. 8

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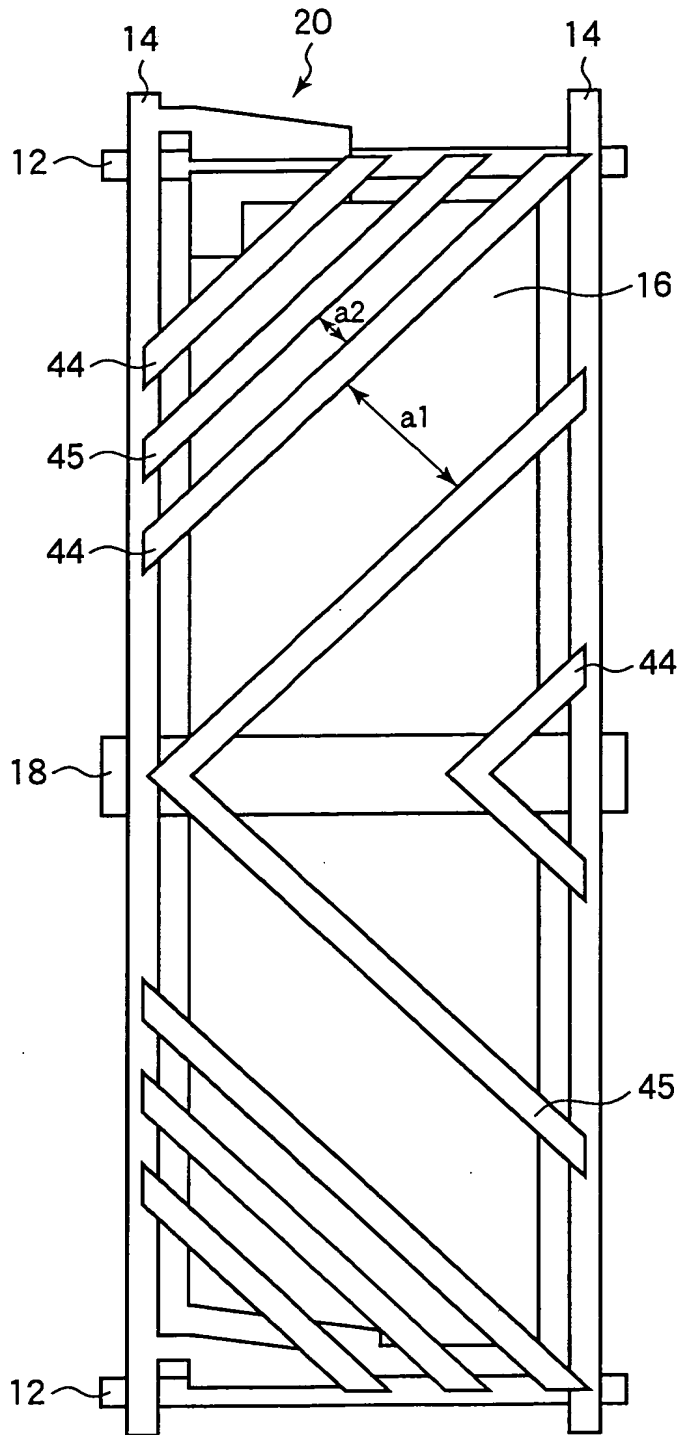


Fig. 9

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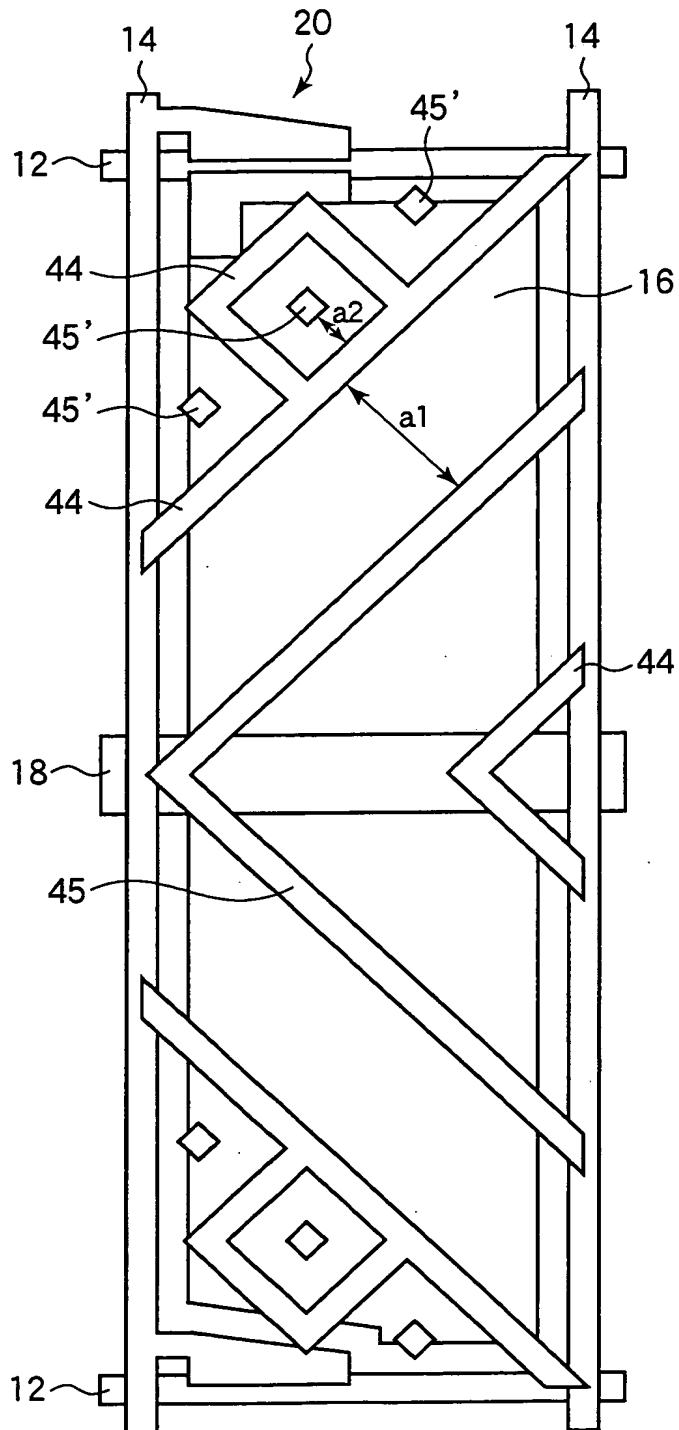


Fig. 10



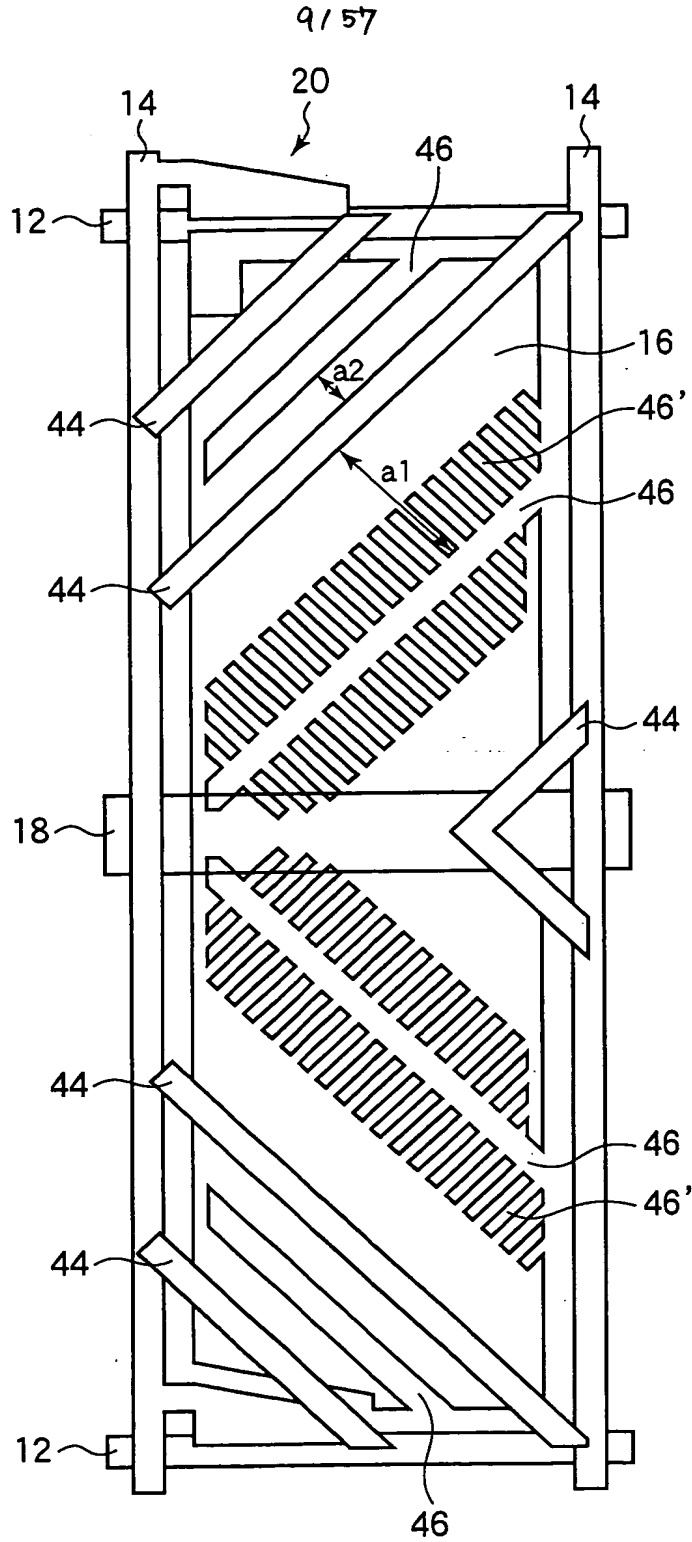


Fig. 11

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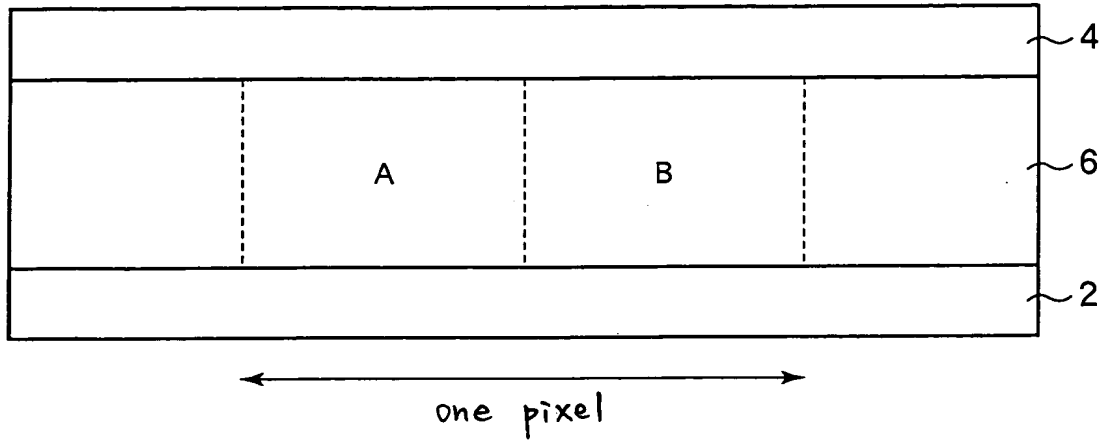


Fig. 12

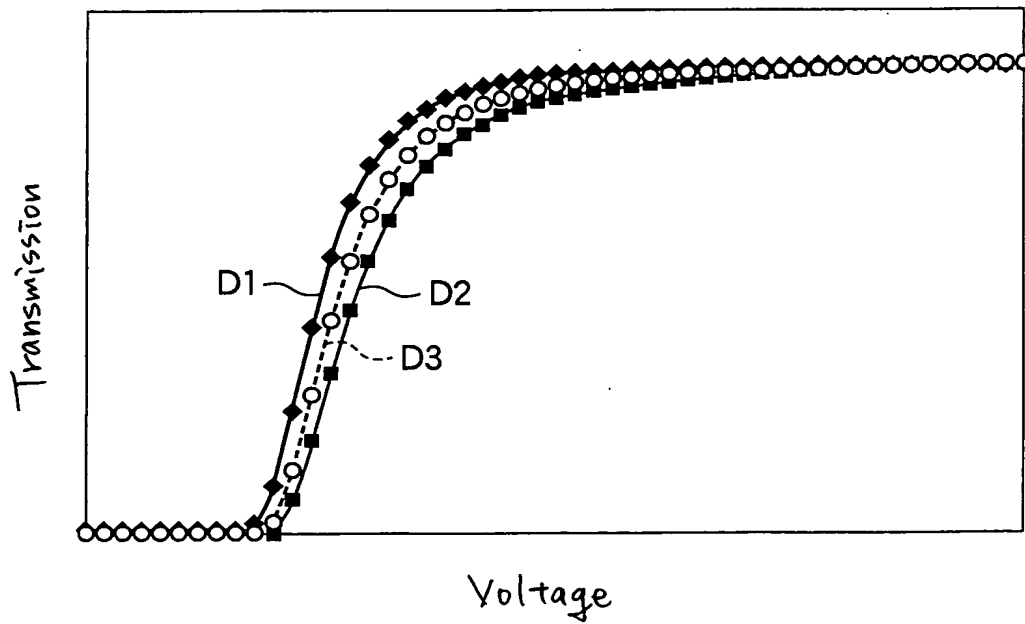


Fig. 13

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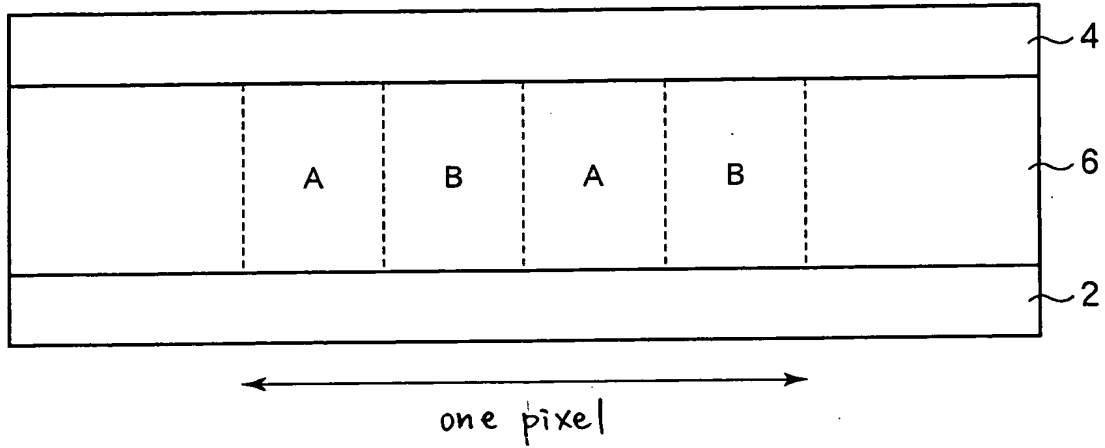


Fig. 14

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Fig. 15A



Fig. 15B

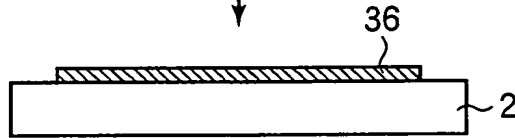


Fig. 15C

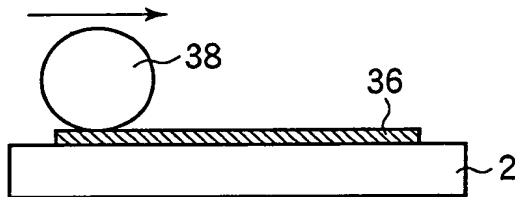


Fig. 15D

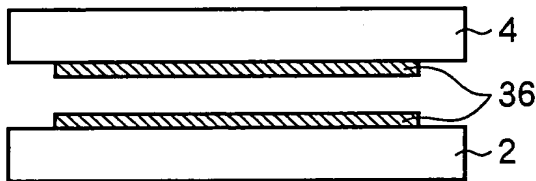


Fig. 15E

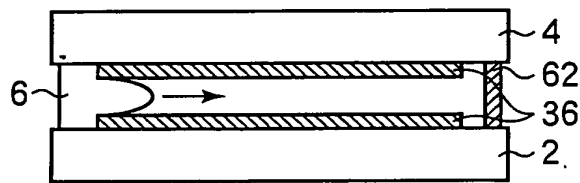
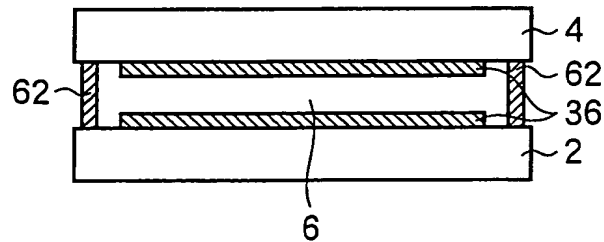


Fig. 15F



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Fig. 16A

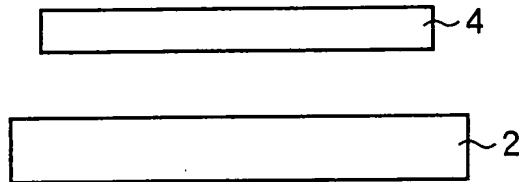


Fig. 16B

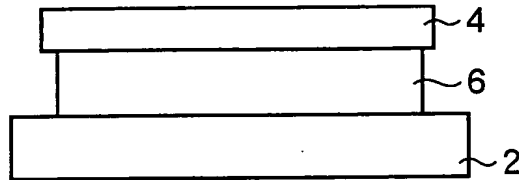
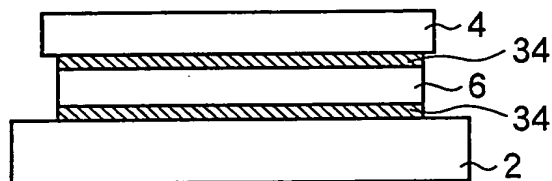


Fig. 16C



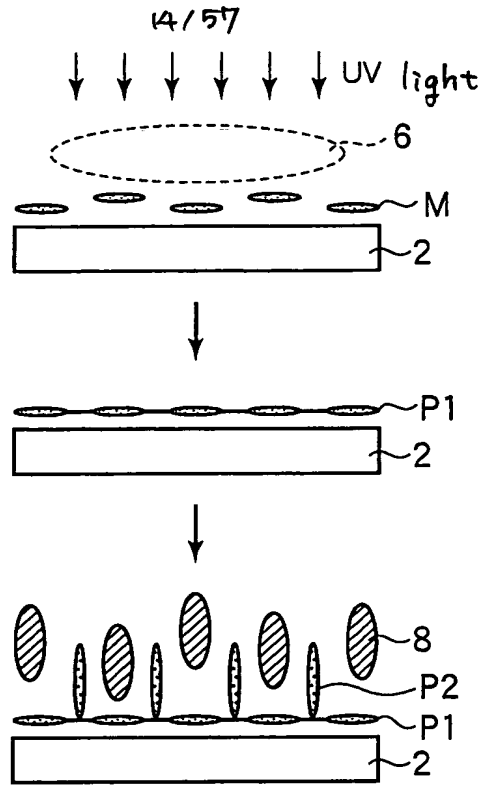


Fig. 17

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Fig. 18A

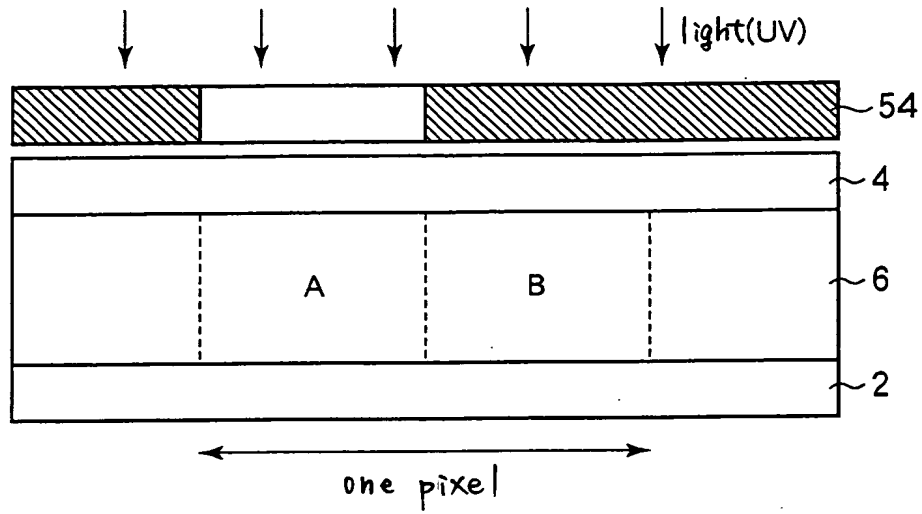
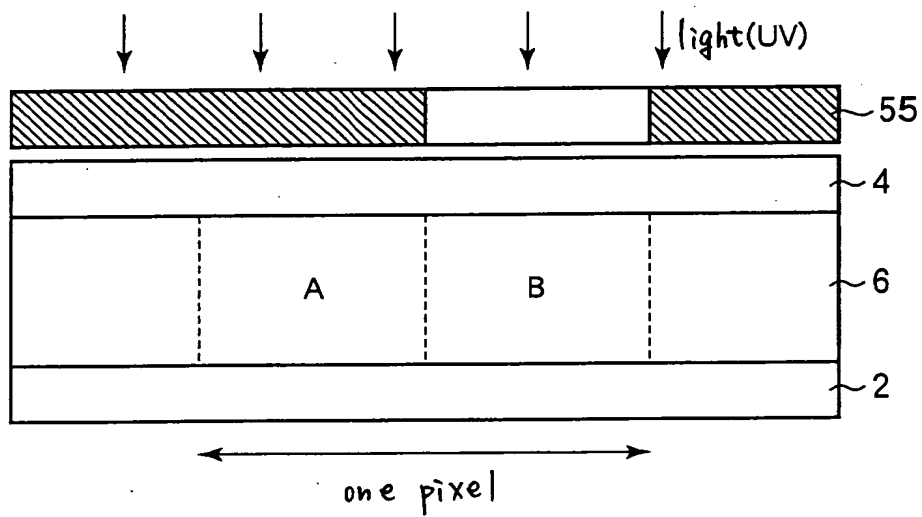


Fig. 18B



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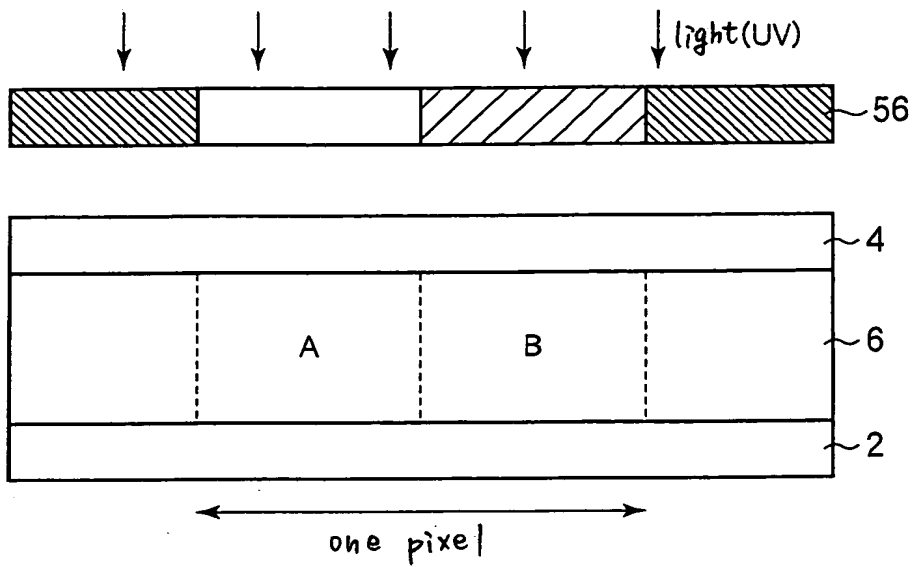


Fig. 19

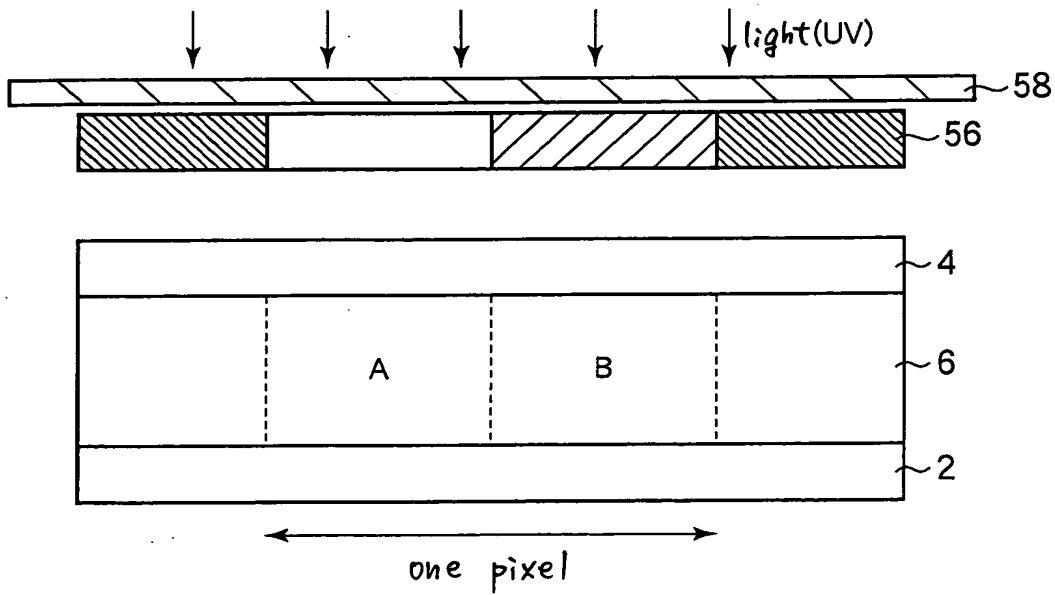


Fig. 20



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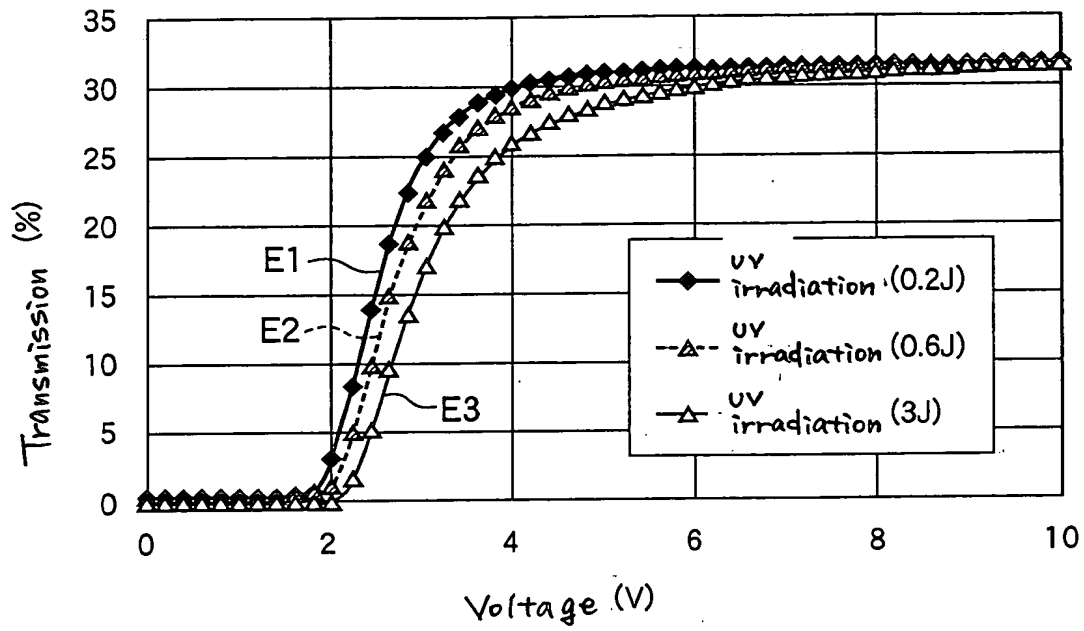


Fig. 21

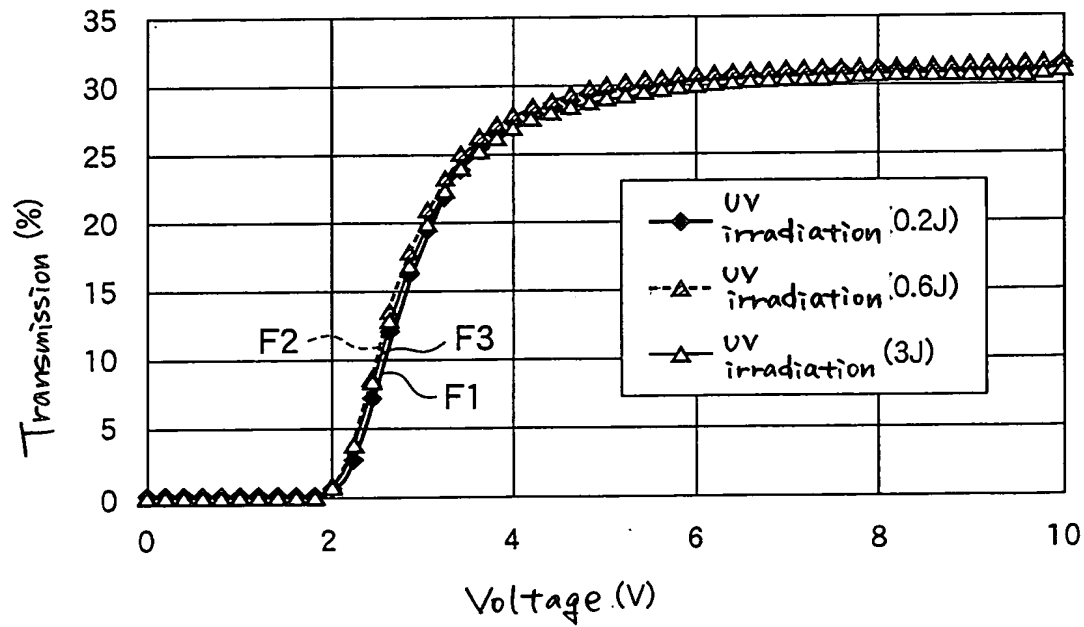


Fig. 22

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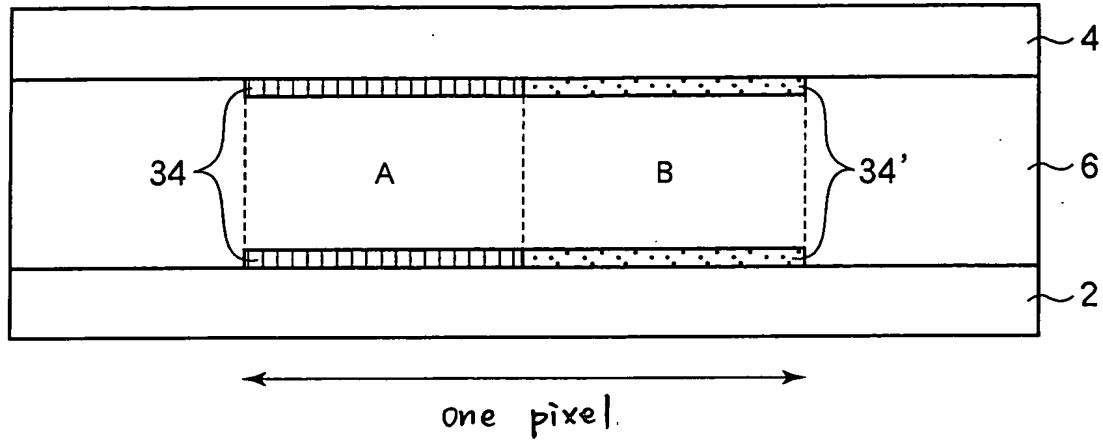


Fig. 23

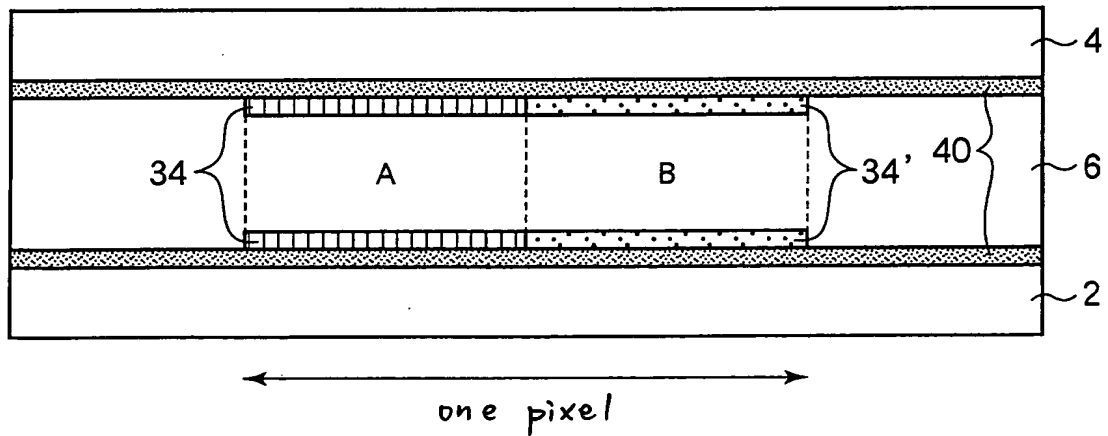


Fig. 24

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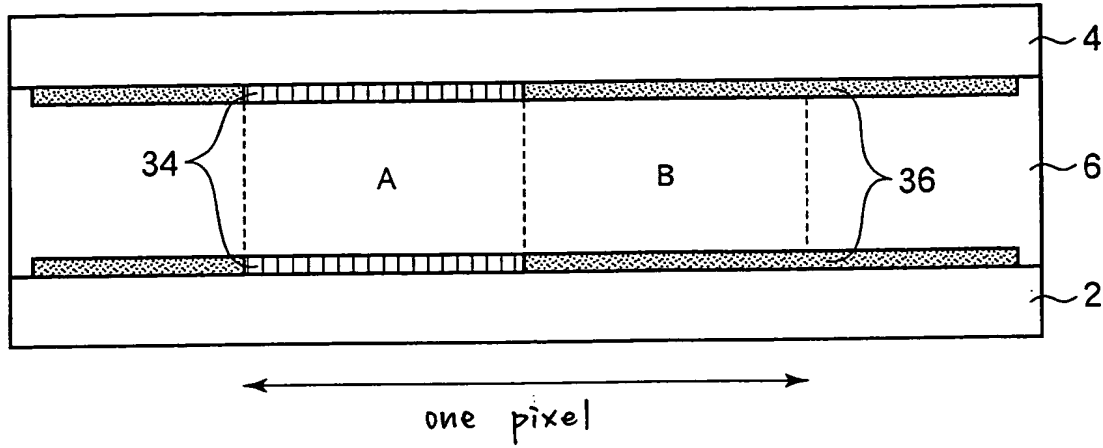


Fig. 25

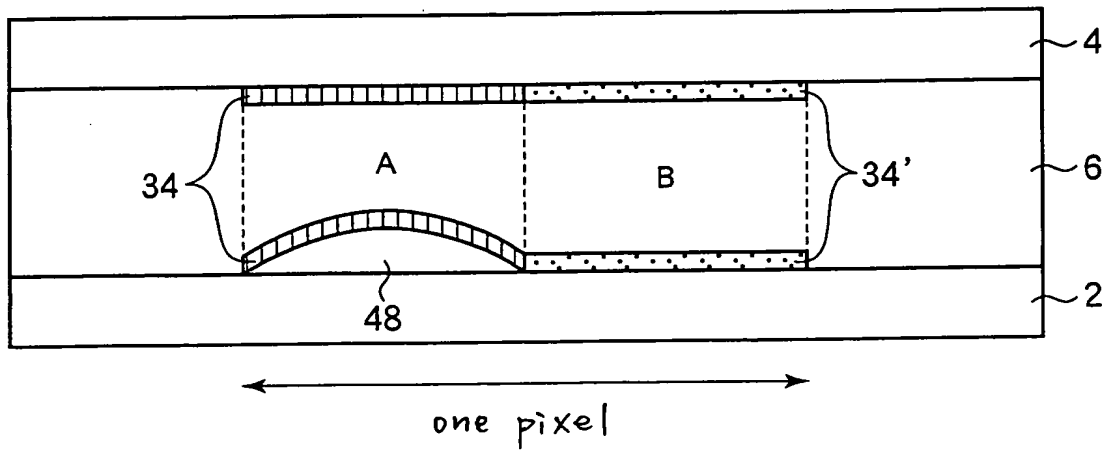


Fig. 26

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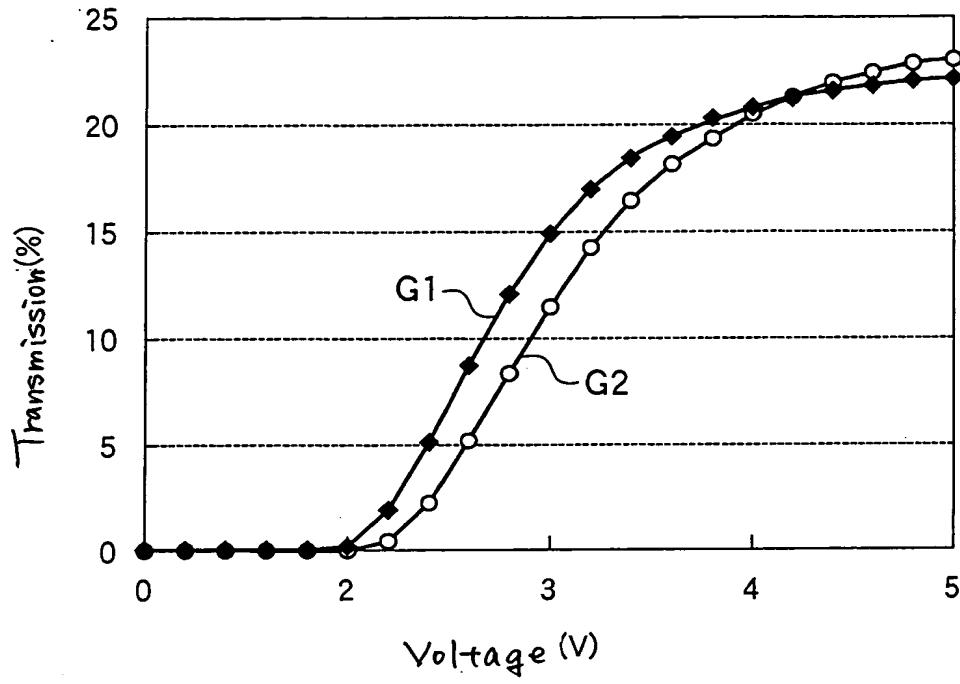


Fig. 27

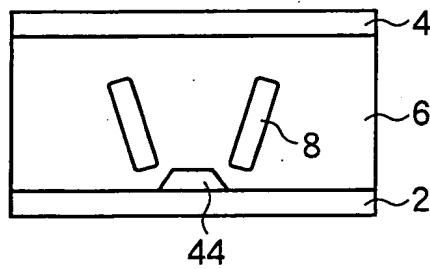


Fig. 28

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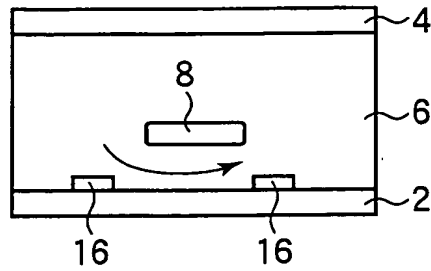


Fig. 29

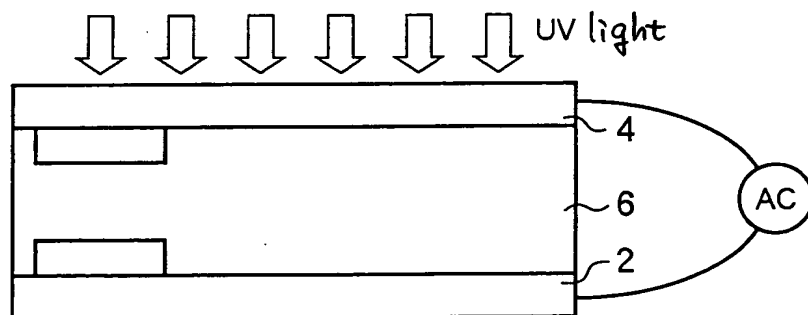


Fig. 30

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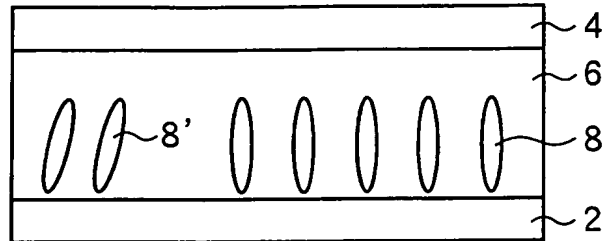


Fig. 31

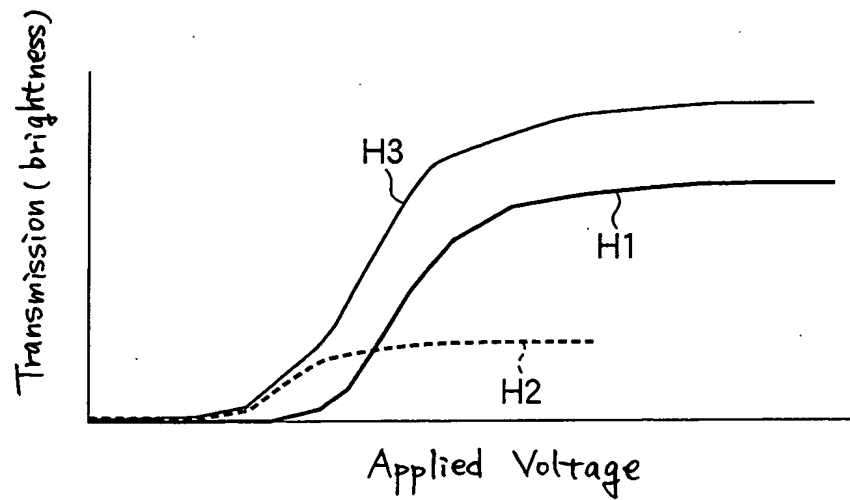


Fig. 32

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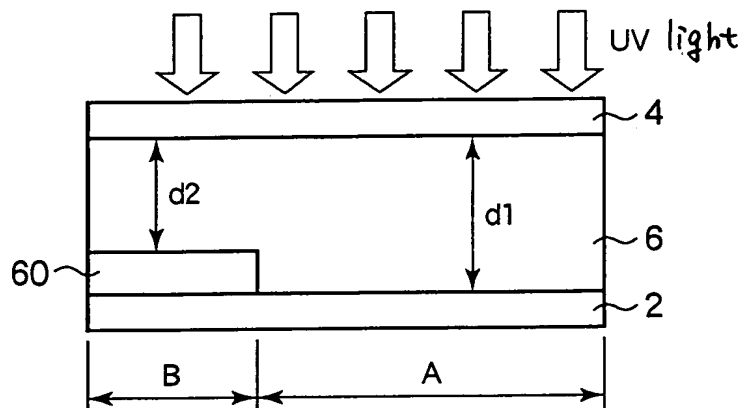


Fig. 33

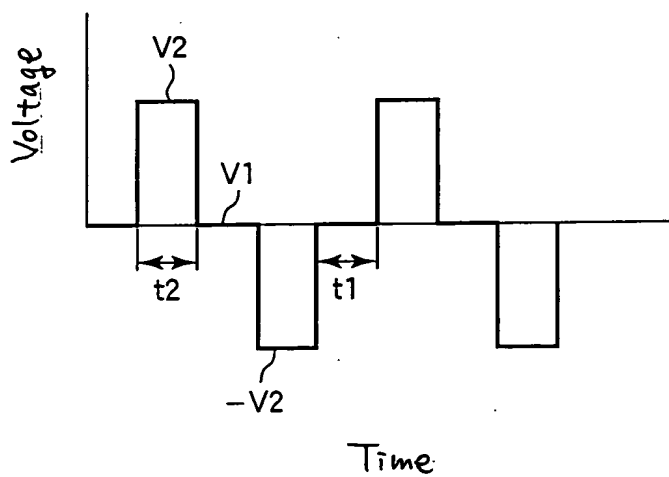


Fig. 34

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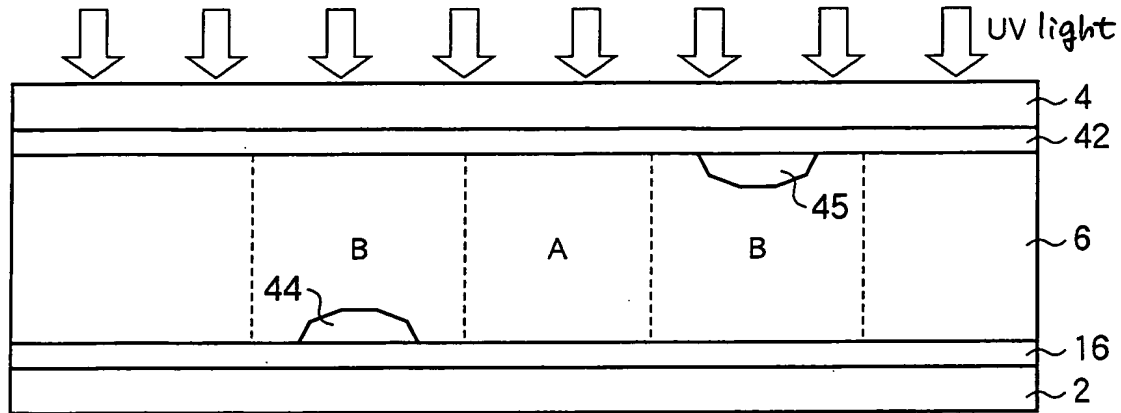


Fig. 35

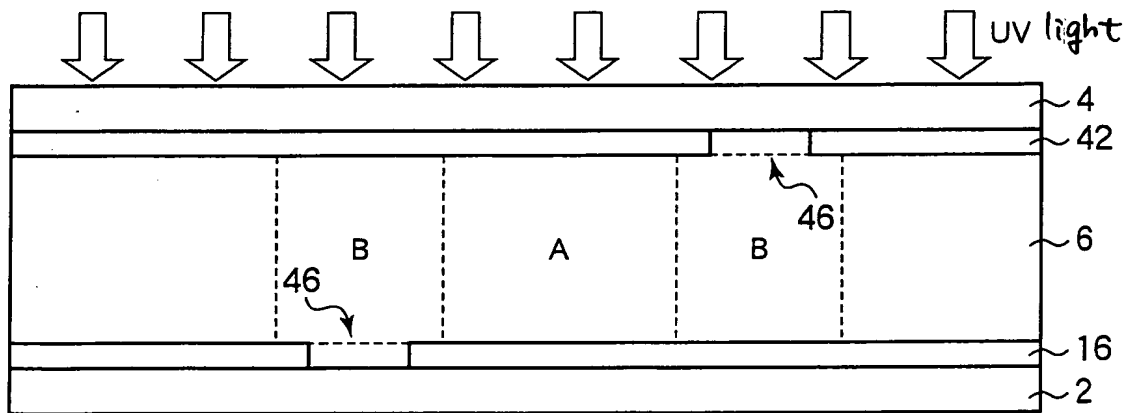


Fig. 36



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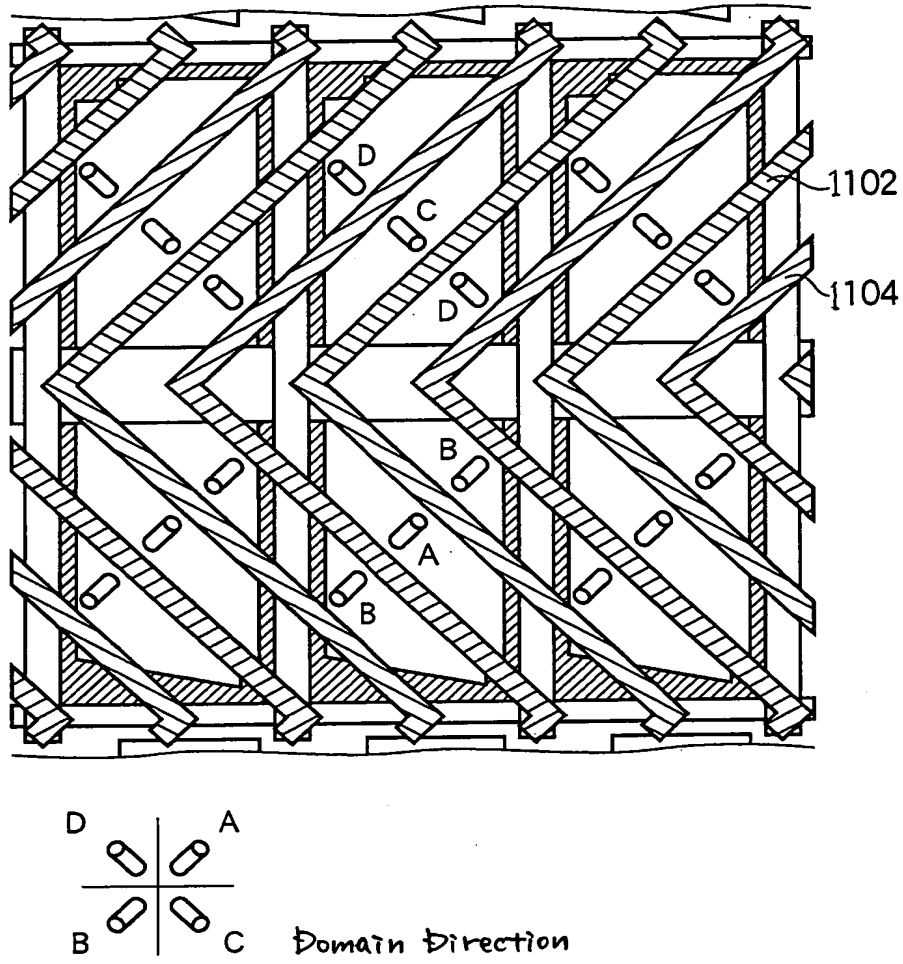


Fig. 37

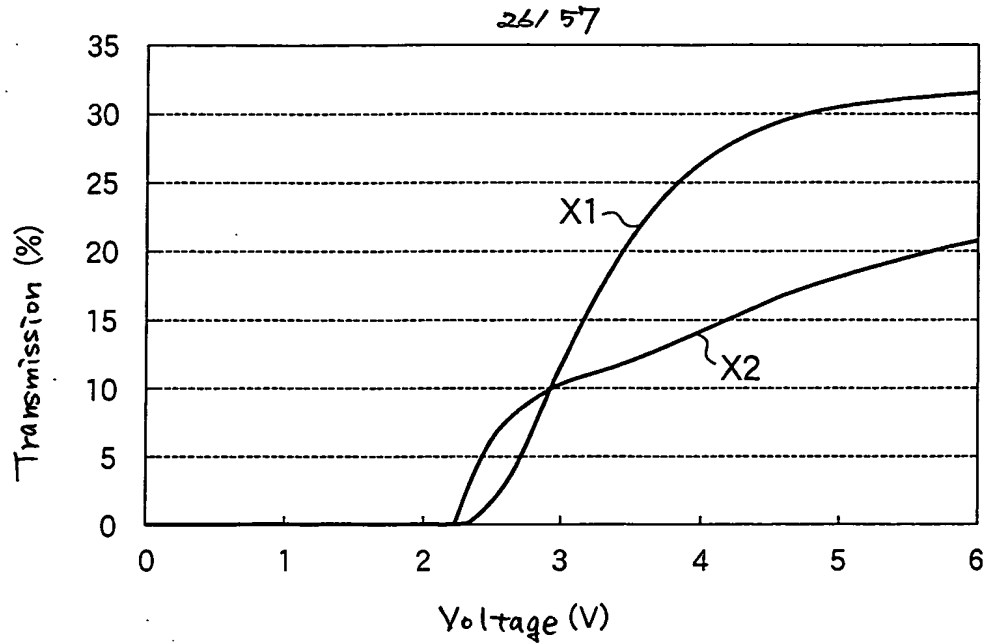


Fig. 38 A

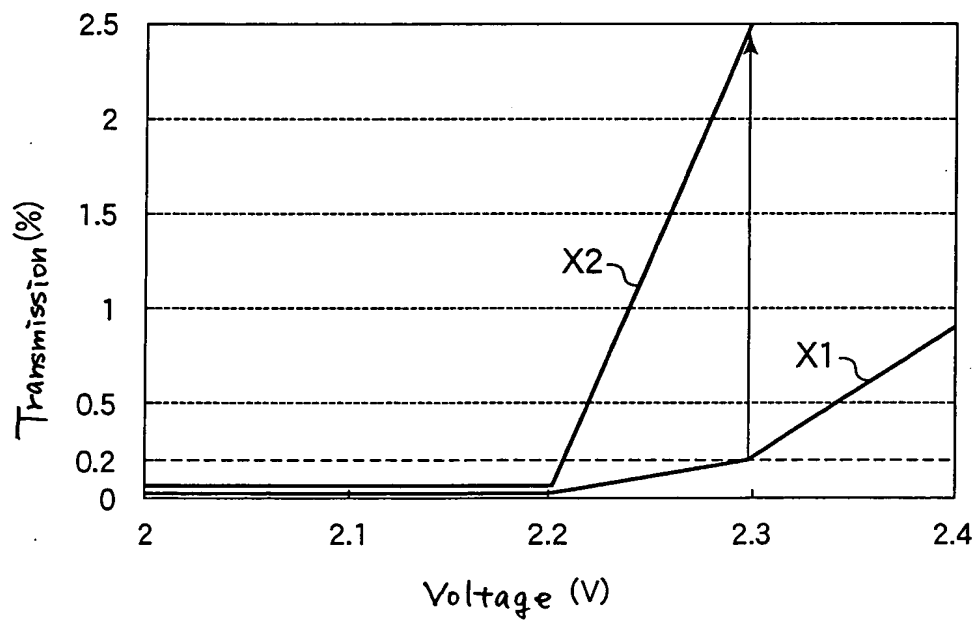


Fig. 38 B

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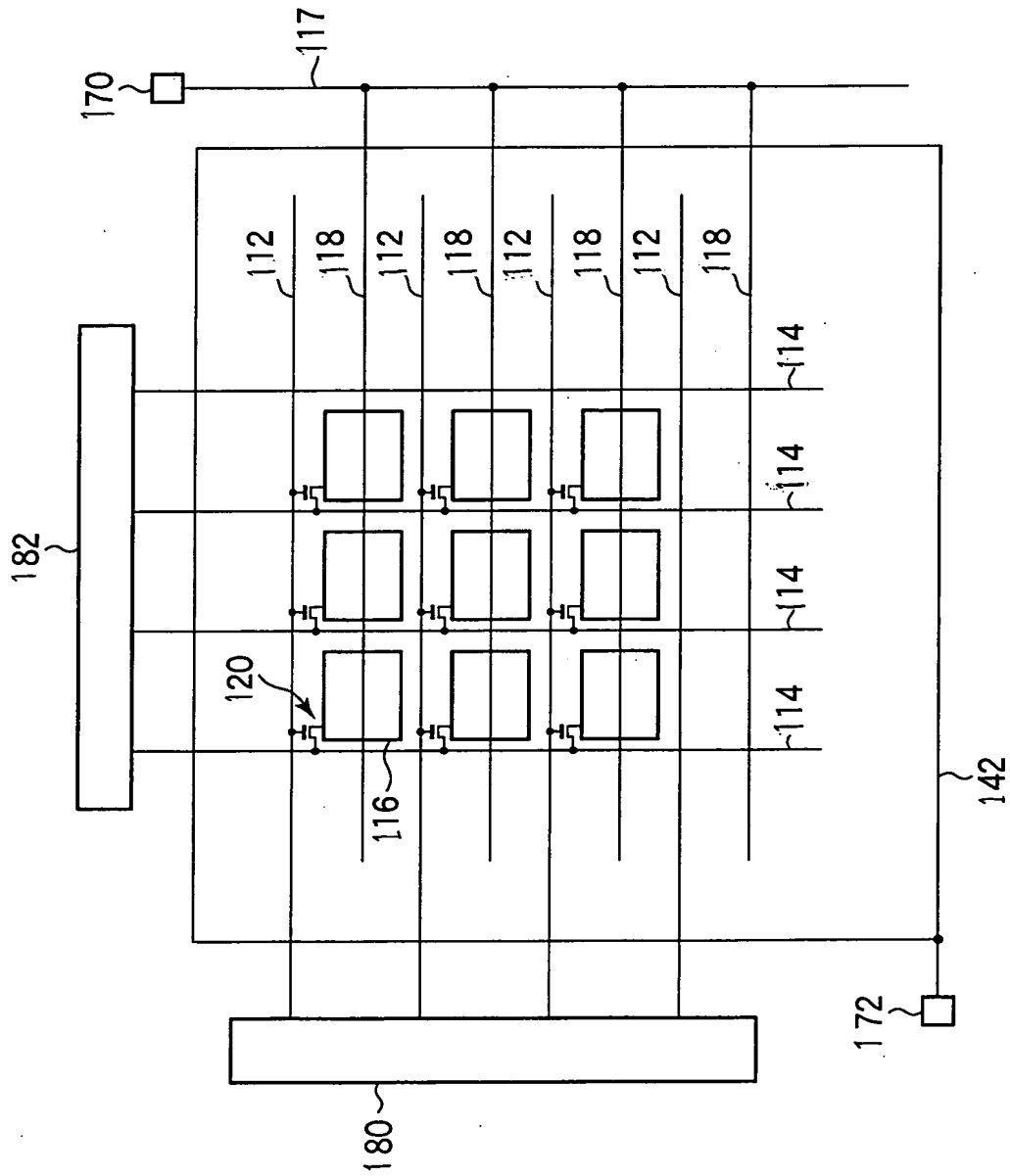


Fig. 39

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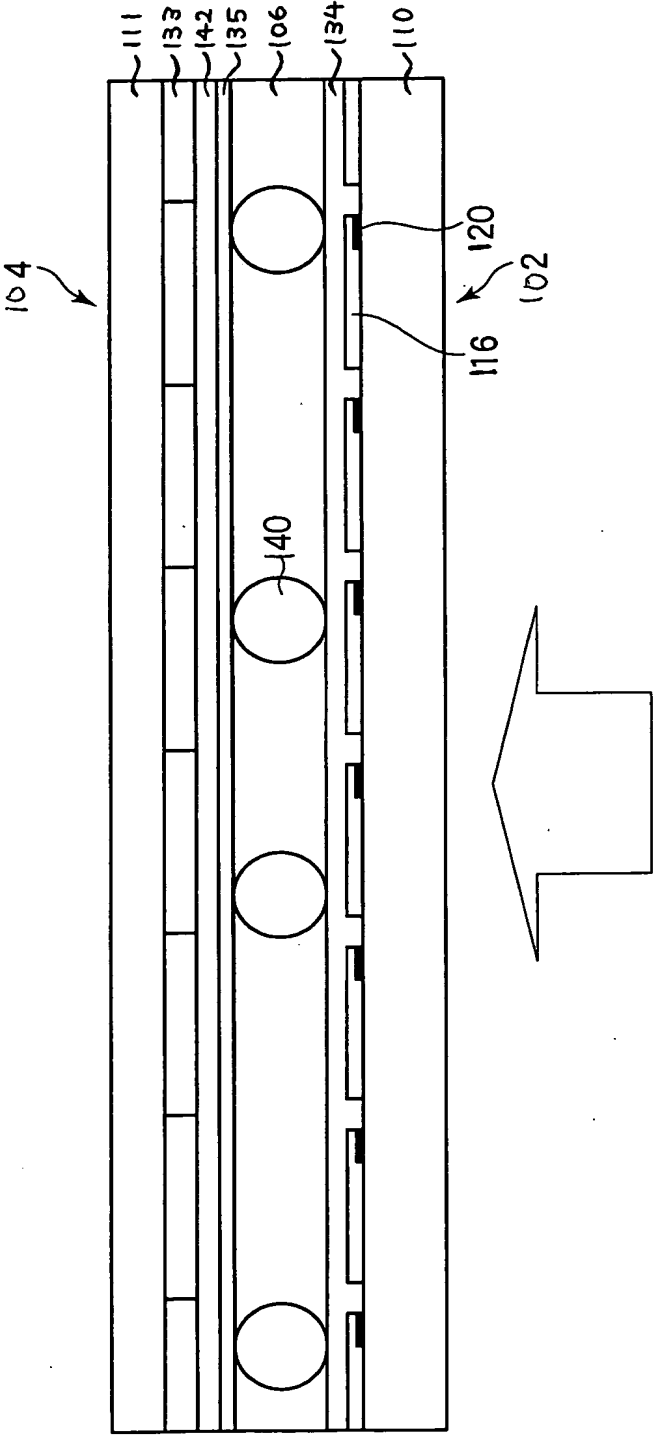


Fig. 40

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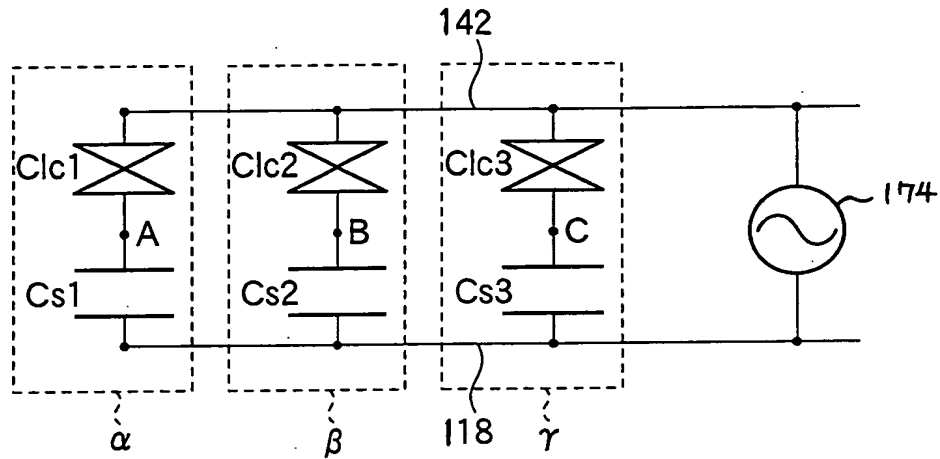


Fig. 41

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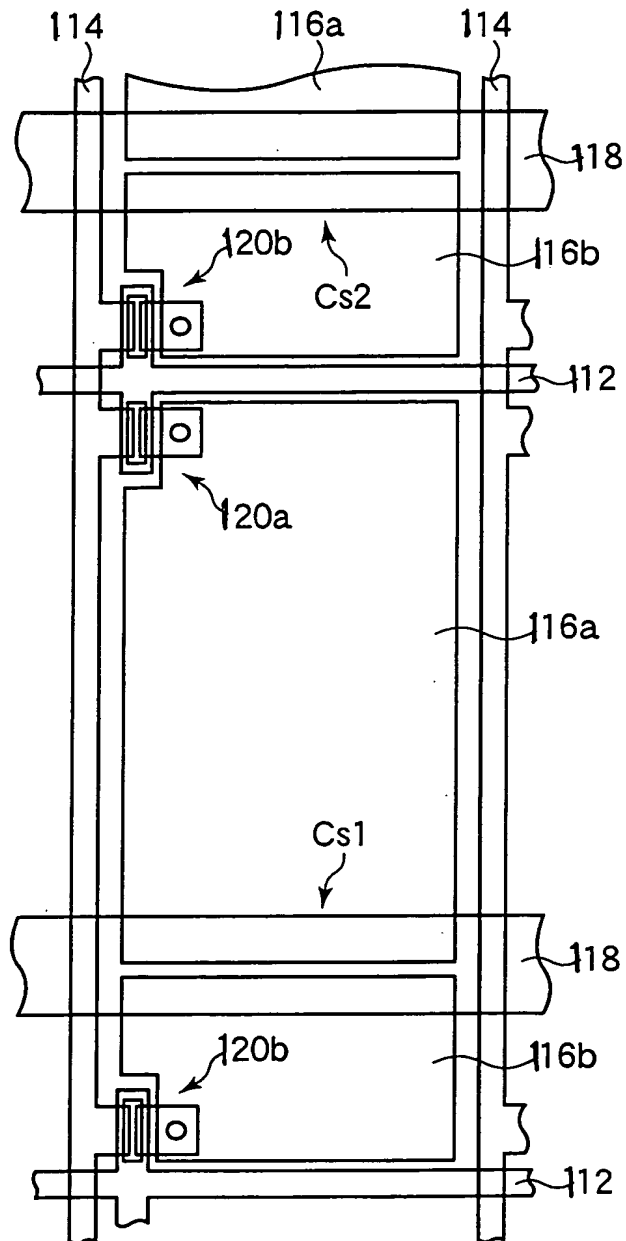


Fig. 42

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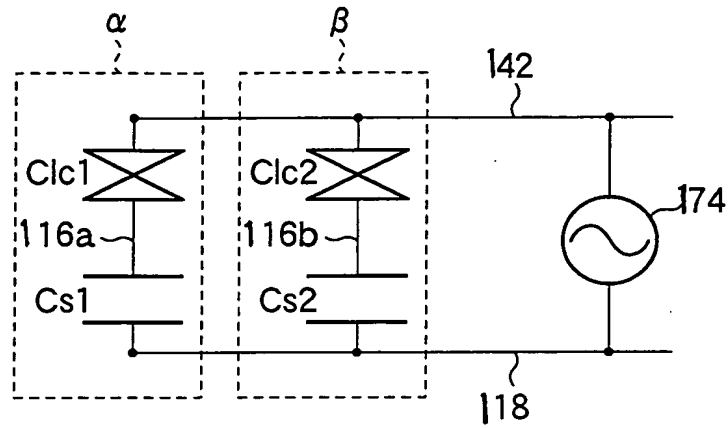


Fig. 43

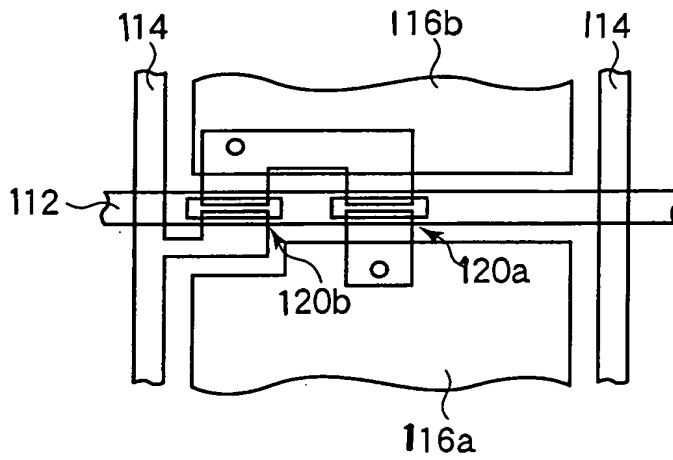


Fig. 44

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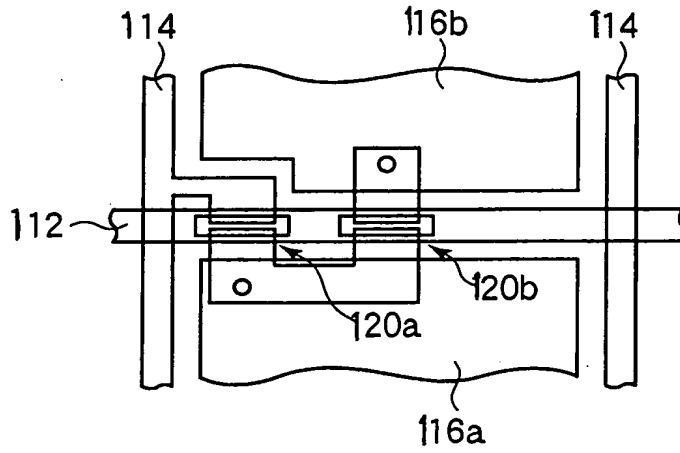


Fig. 45



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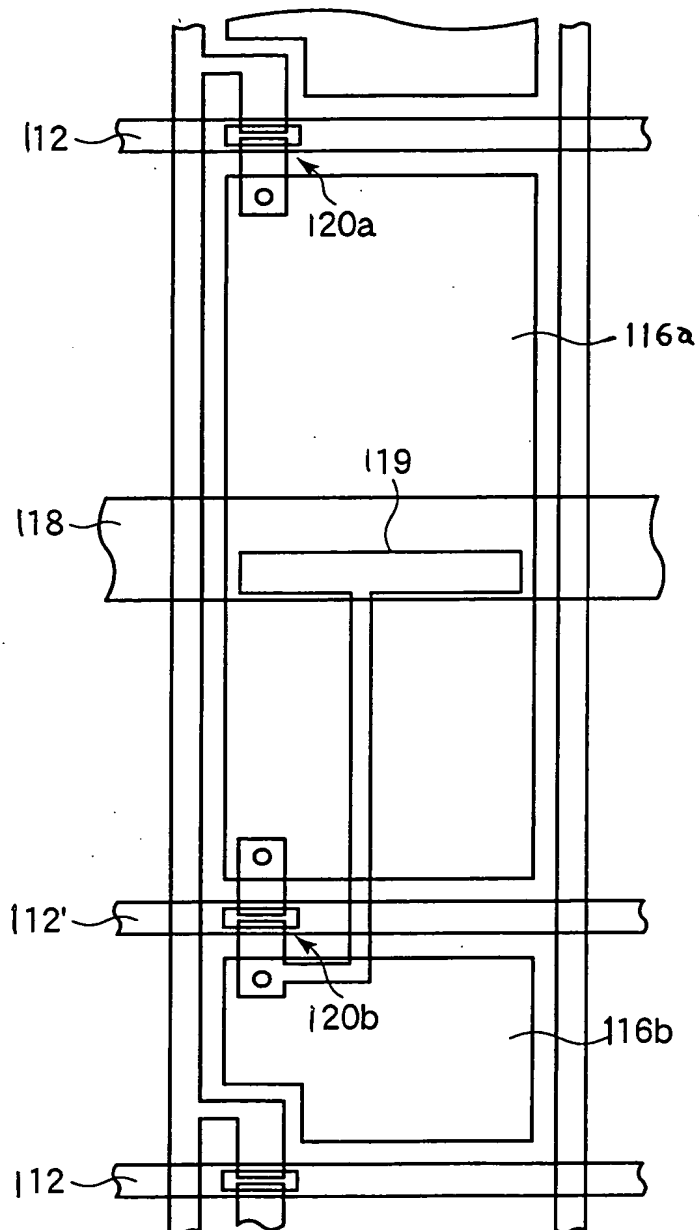


Fig. 46

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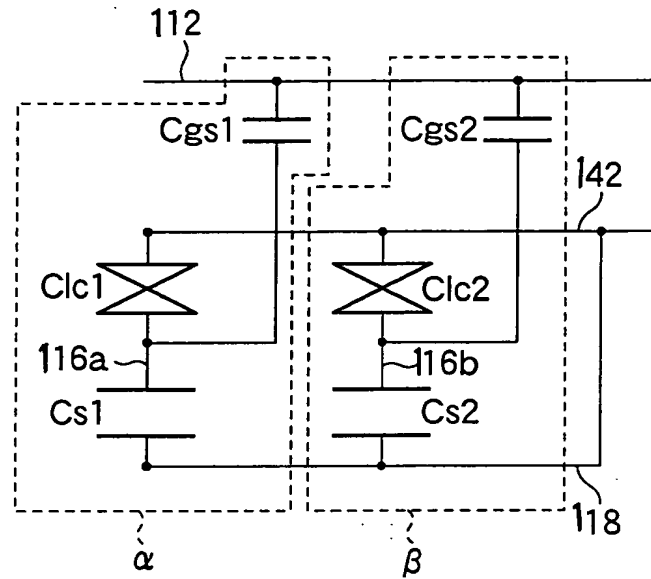


Fig. 47

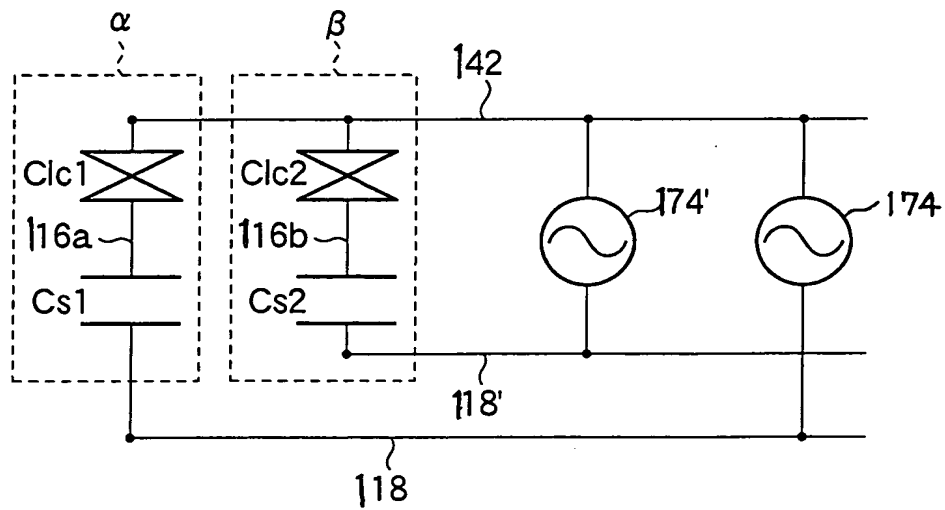


Fig. 48

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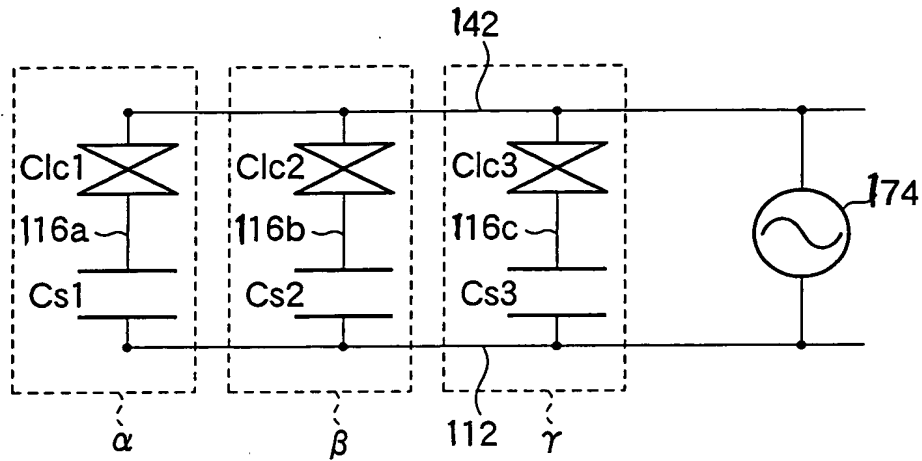


Fig. 49

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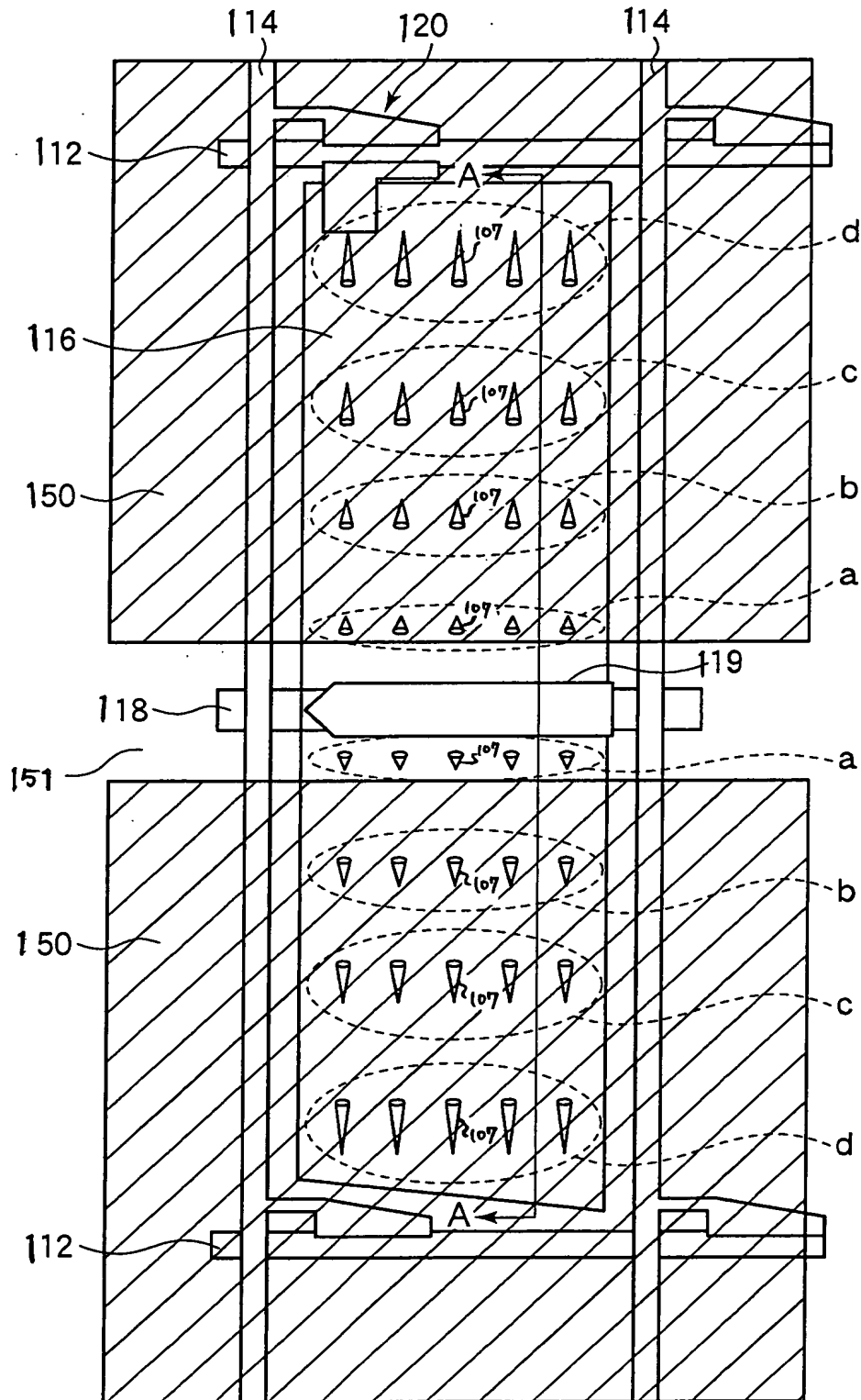


Fig. 50

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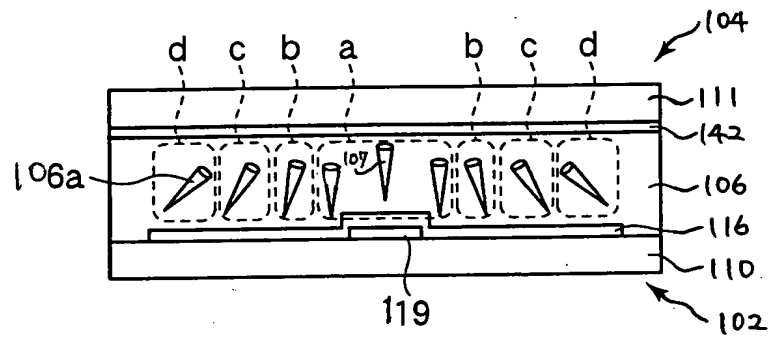


Fig. 51

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Fig. 52A

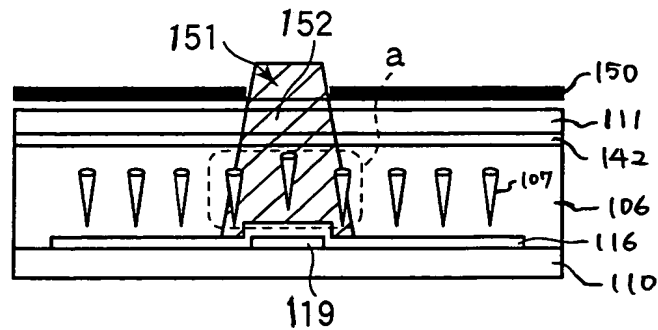


Fig. 52B

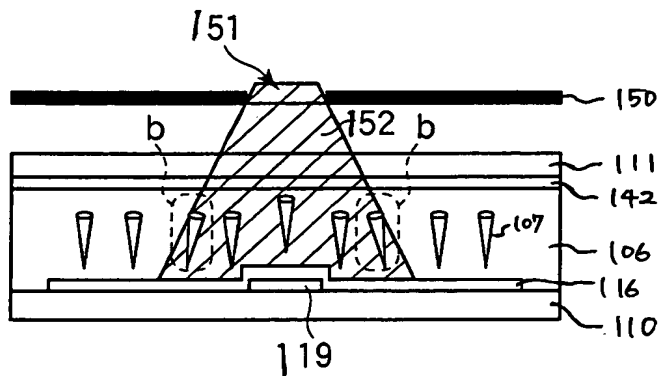


Fig. 52C

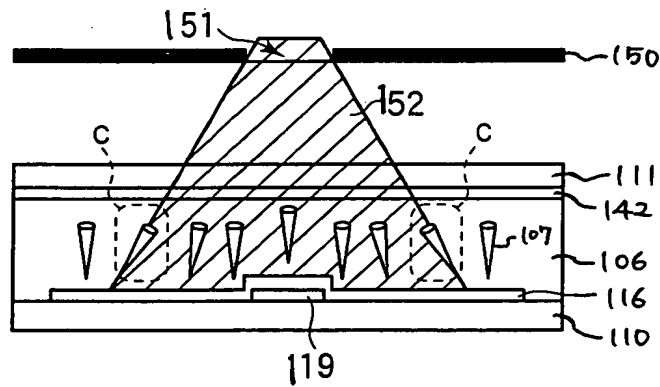
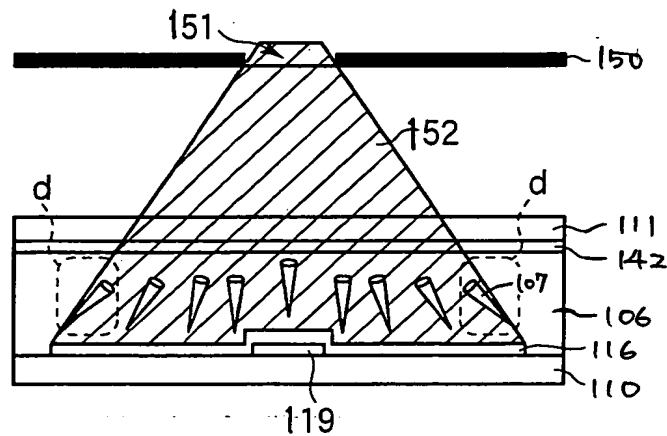


Fig. 52D



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Fig. 53A

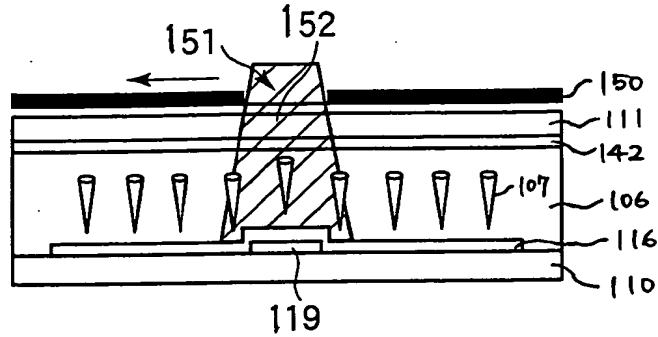


Fig. 53B

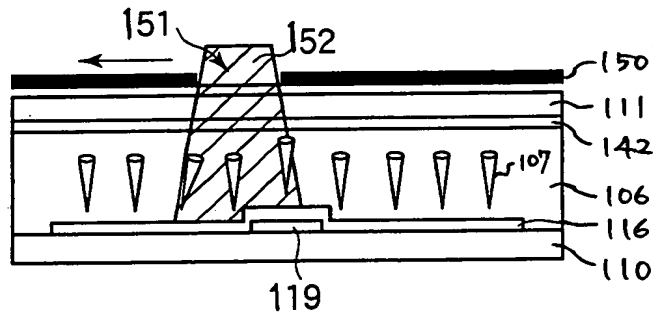


Fig. 53C

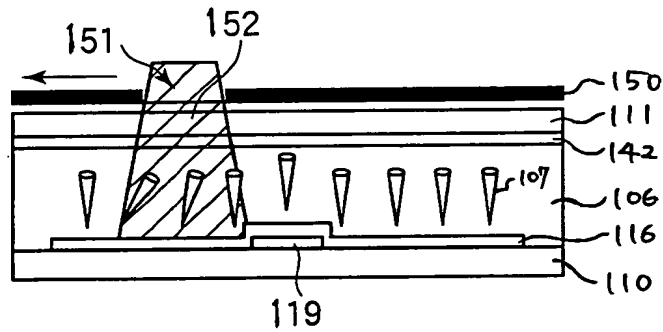
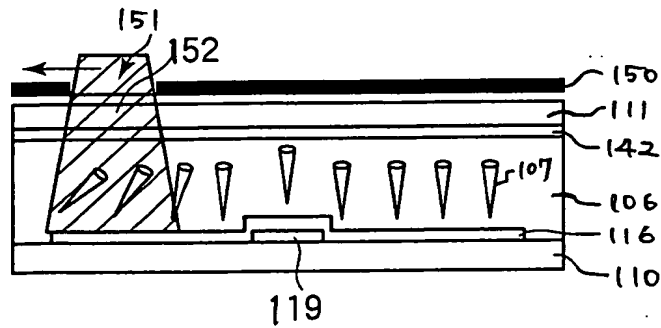


Fig. 53D



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Fig. 54A

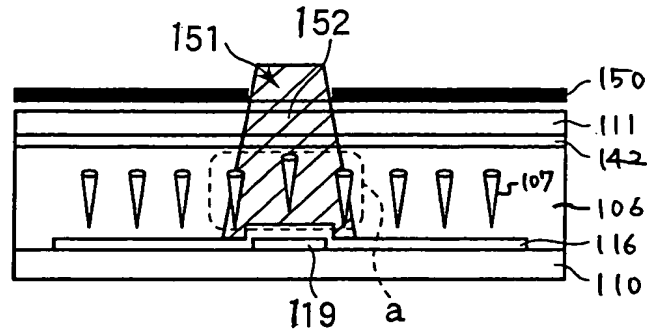


Fig. 54B

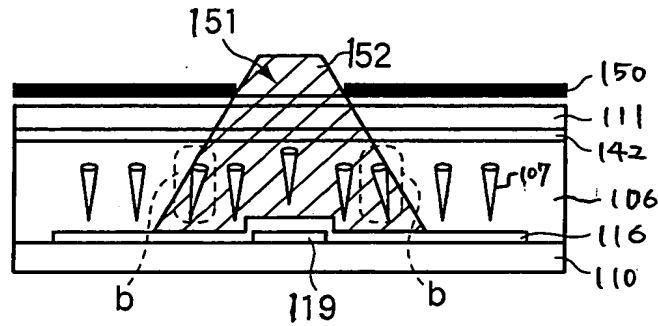


Fig. 54C

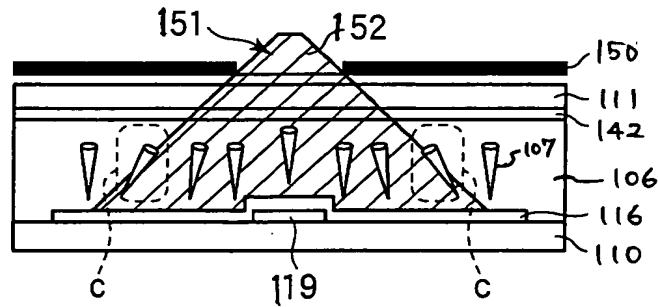
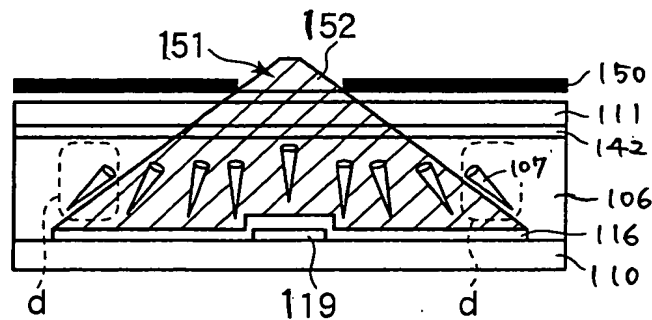


Fig. 54D





This cross-sectional view shows a tapered structure 151 on a substrate 110. The structure 151 has a top surface 152 and a side surface 154. It is formed on a layer 111, which is on top of a layer 142. Below these is a layer 106, which contains several vertical structures 107. A layer 116 is located between the layer 106 and the substrate 110. A dashed line 119 indicates a cross-section through the structure 151. The substrate 110 is shown at the bottom, and the top surface of the structure 151 is labeled 152. The side surface of the structure 151 is labeled 154. The layer 111 is the topmost layer of the structure. The layer 142 is a thin layer below 111. The layer 106 is a thicker layer below 142. The vertical structures 107 are located within the layer 106. The layer 116 is a thin layer below 106. The substrate 110 is the base of the device. The dashed line 119 indicates a cross-section through the structure 151. The top surface of the structure 151 is labeled 152. The side surface of the structure 151 is labeled 154. The layer 111 is the topmost layer of the structure. The layer 142 is a thin layer below 111. The layer 106 is a thicker layer below 142. The vertical structures 107 are located within the layer 106. The layer 116 is a thin layer below 106. The substrate 110 is the base of the device.

A cross-sectional view of a semiconductor device. A central dome-shaped structure, labeled 152, is formed on a substrate. The dome is covered by a layer labeled 151. Below the dome, a series of vertical structures, labeled 107, are visible. The device is composed of several layers: 154 (top), 111, 142, 106, 116, and 110 (bottom). A central rectangular feature is labeled 119. The device is shown in a cross-section with dashed lines indicating the edges, labeled 'd'.

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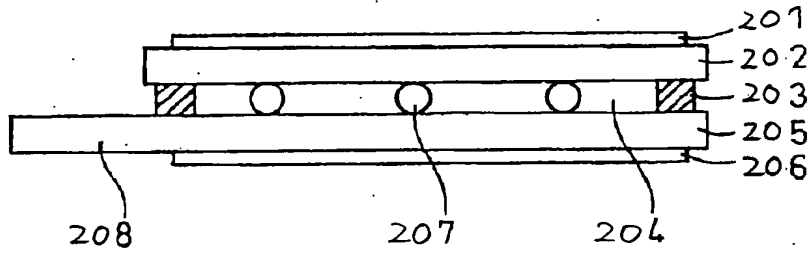


Fig. 56

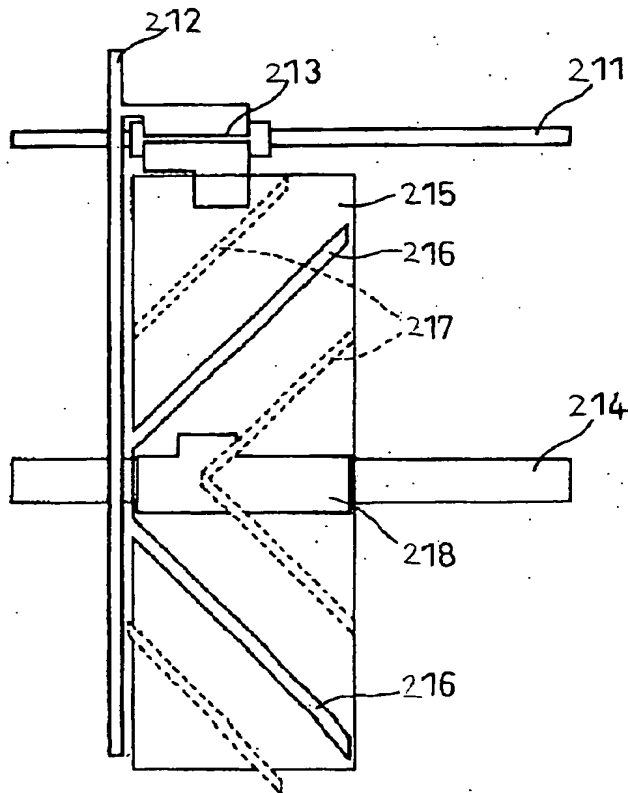


Fig. 57

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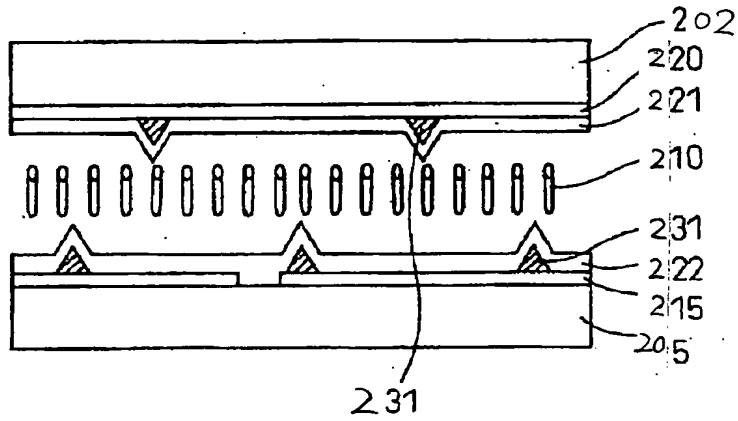


Fig. 58A

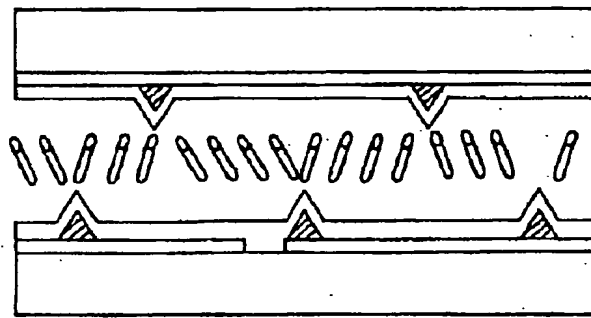


Fig. 58B

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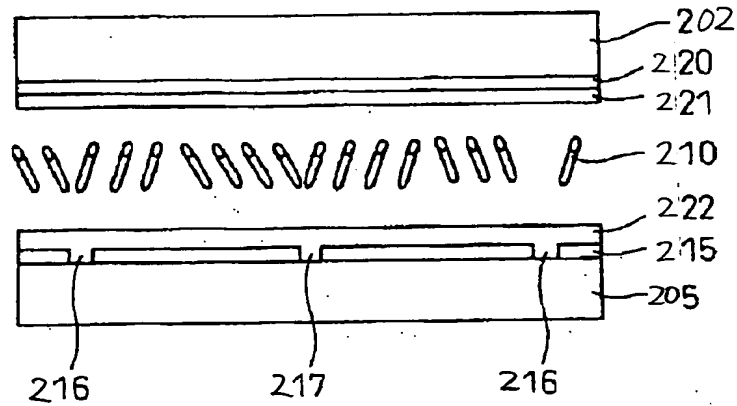


Fig. 59

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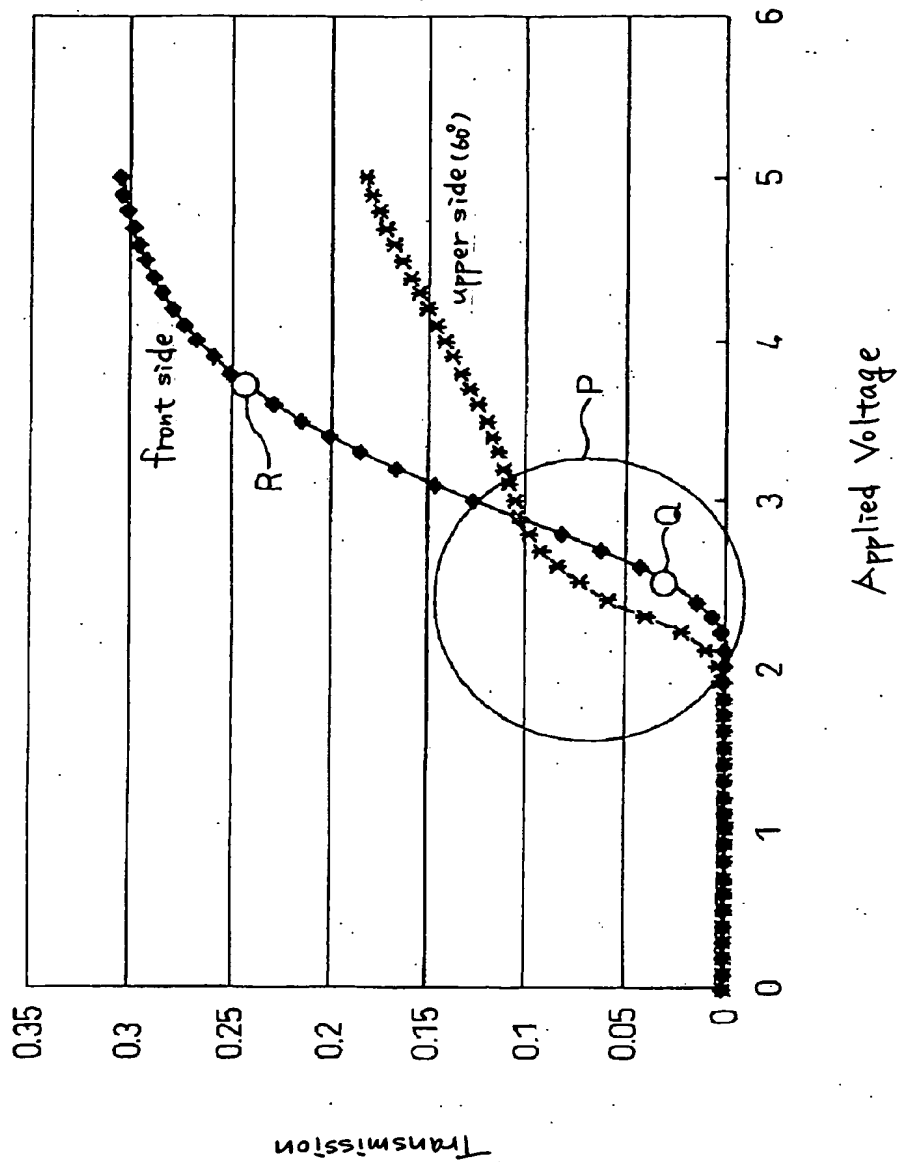


Fig. 60

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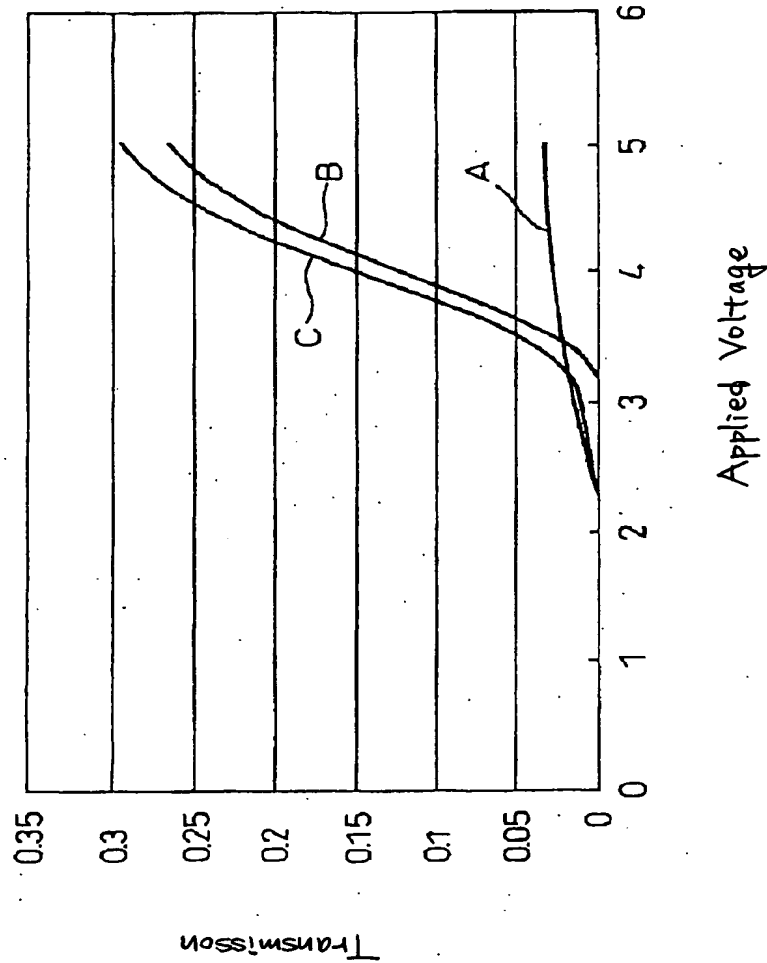


Fig. 61

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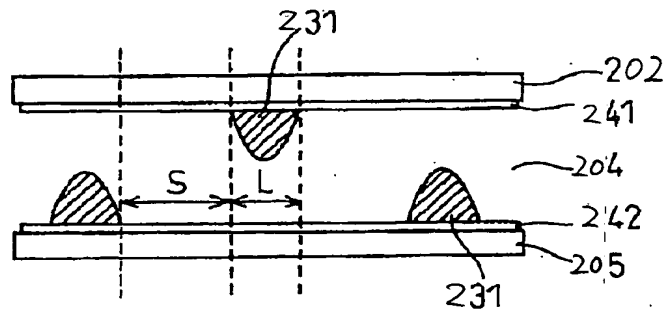


Fig. 62A

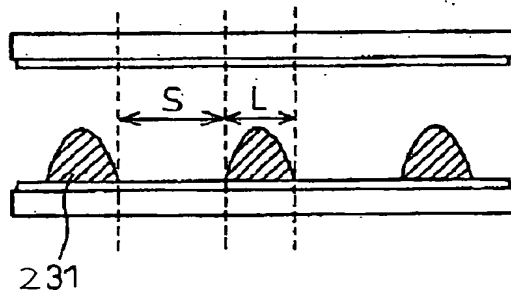


Fig. 62B

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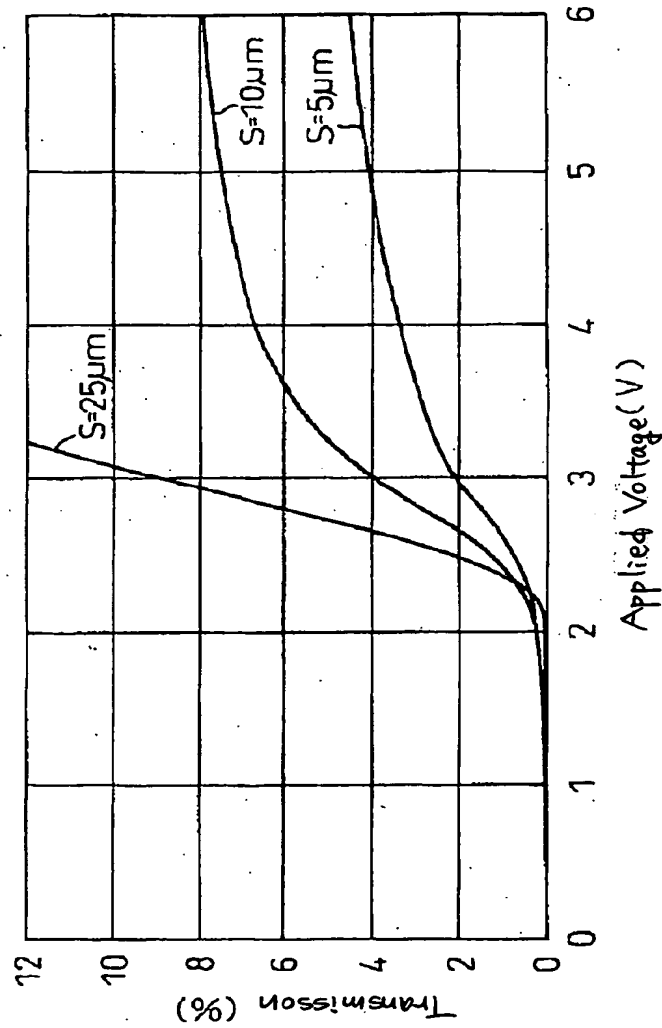


Fig. 63



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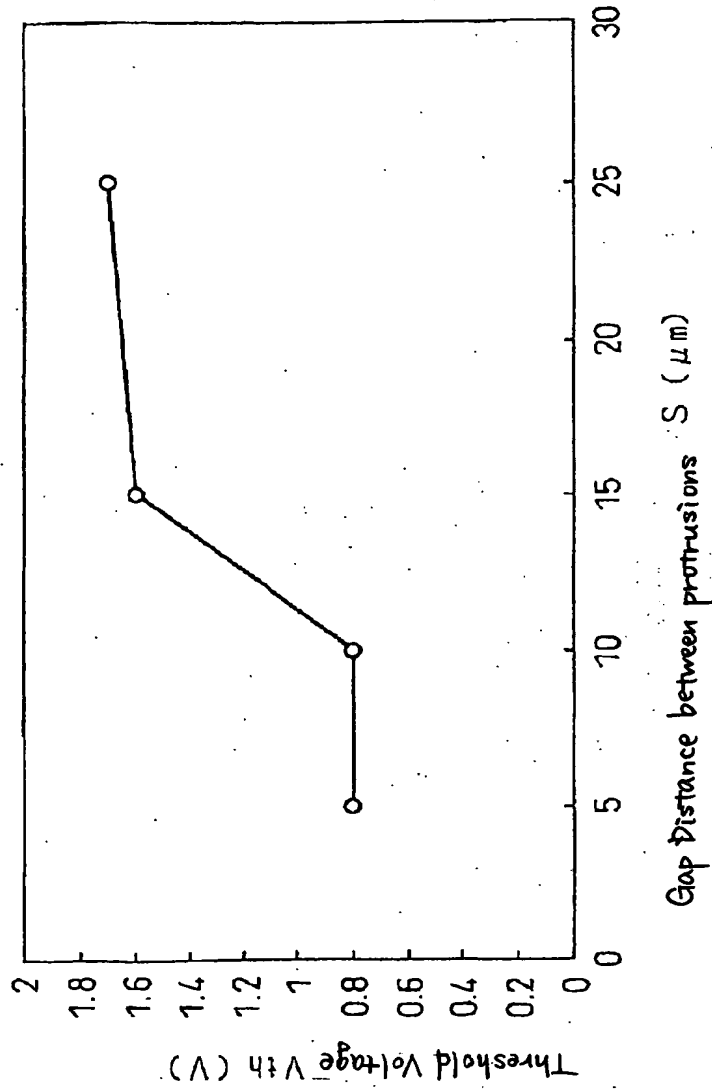


Fig. 64

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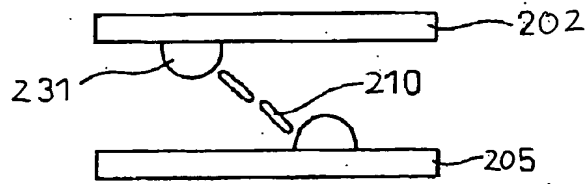


Fig. 65A

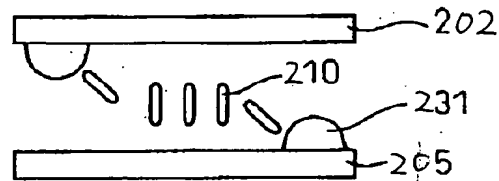


Fig. 65B

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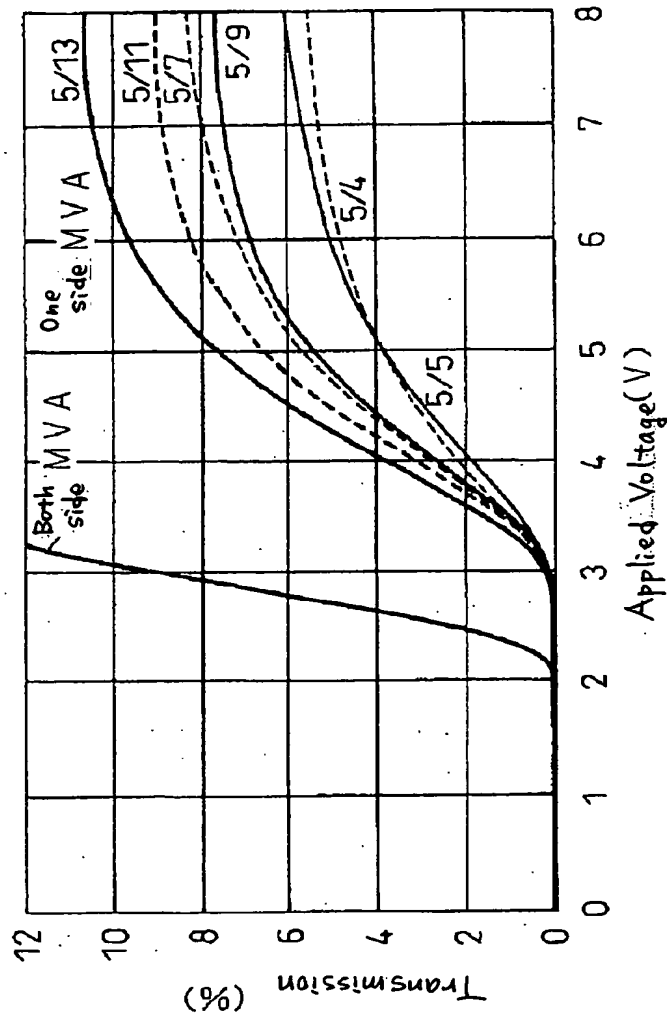


Fig. 66

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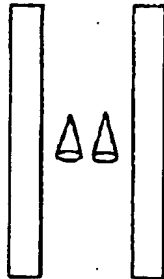


Fig. 67C

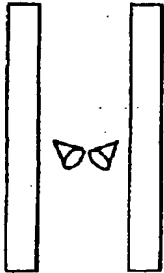


Fig. 67B

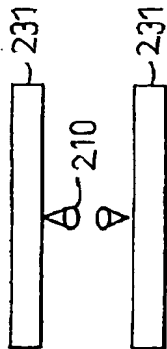


Fig. 67A

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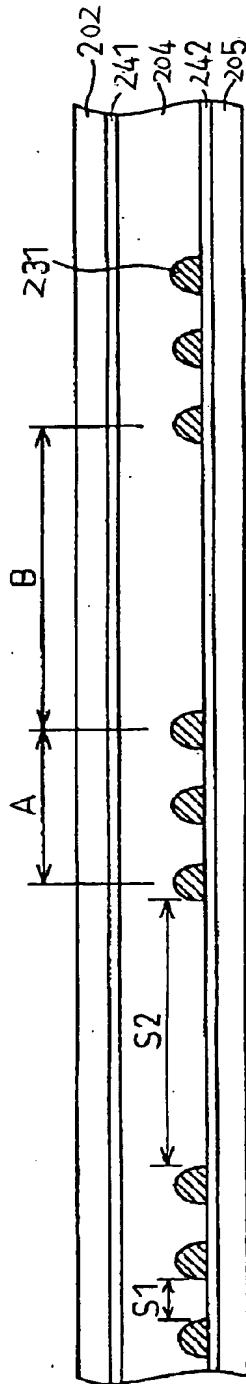


Fig. 68A

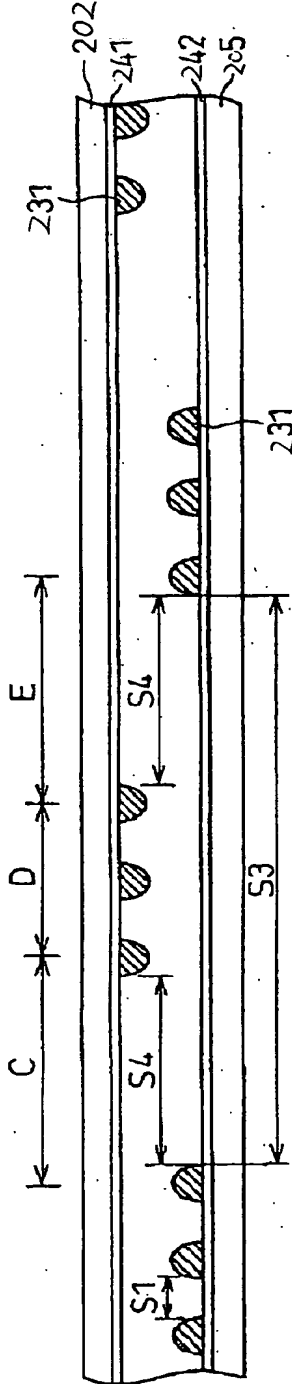


Fig. 68B

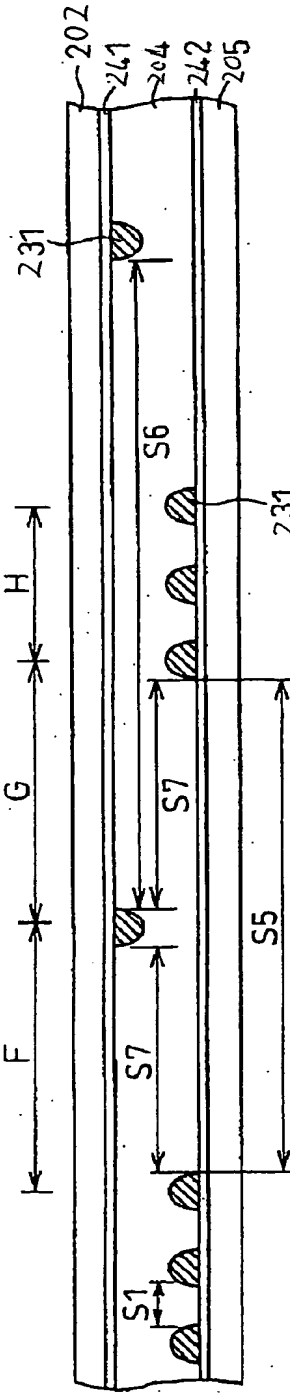


Fig. 68C

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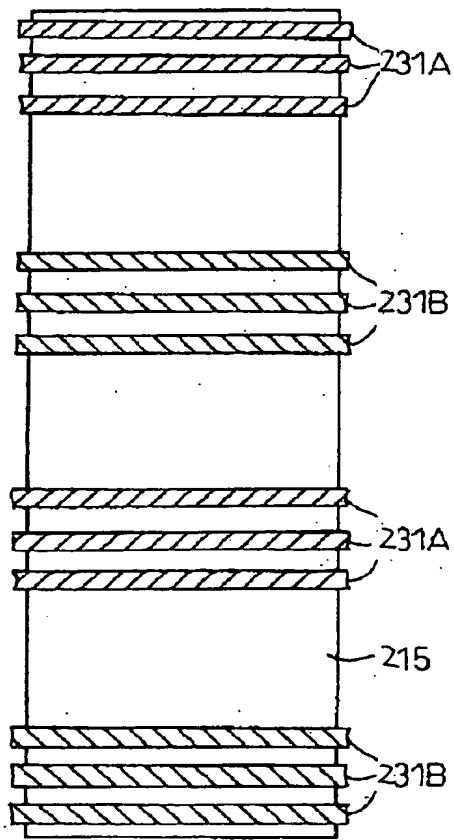


Fig. 69A

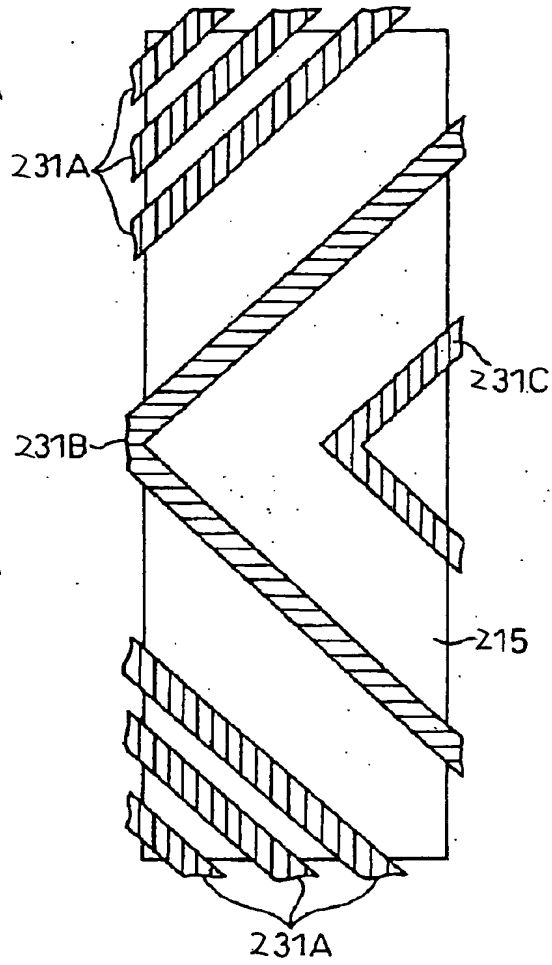


Fig. 69B

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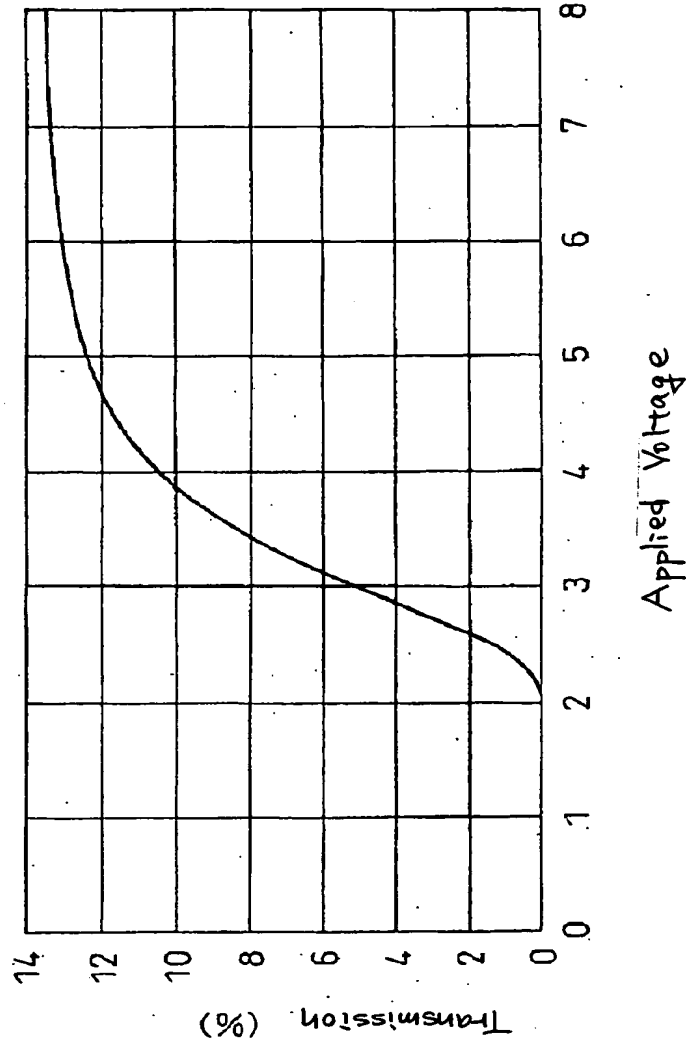


Fig. 70

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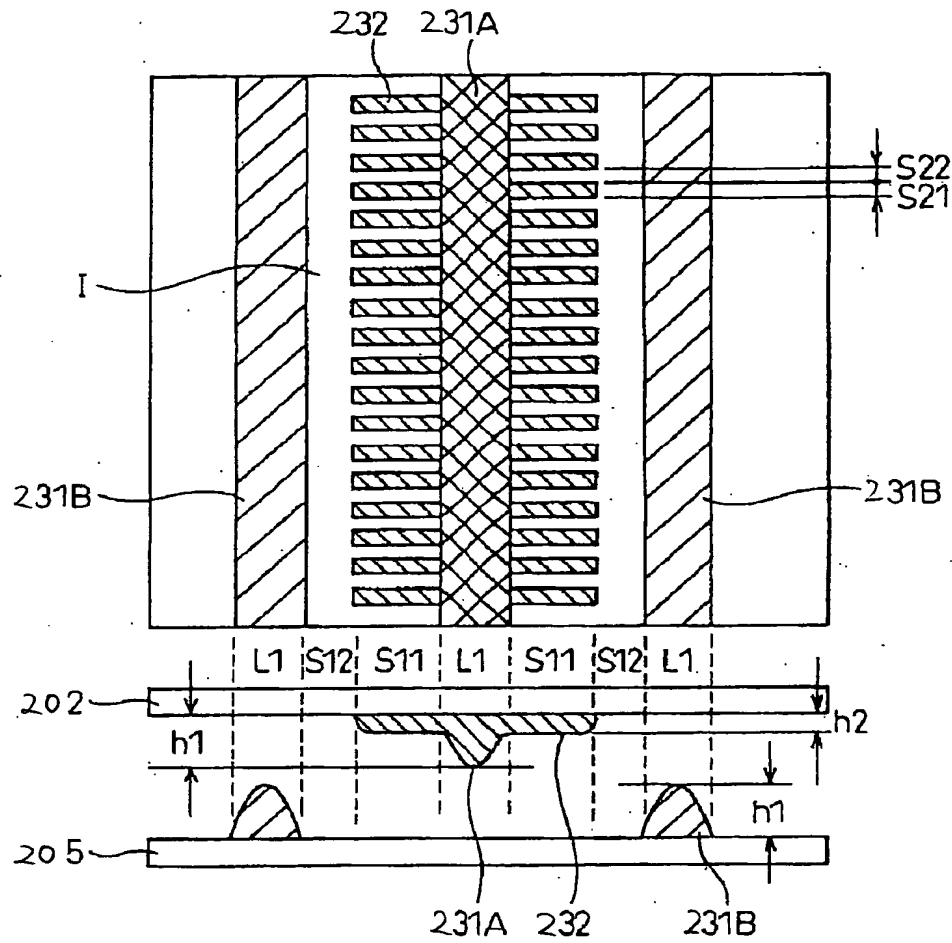


Fig. 71



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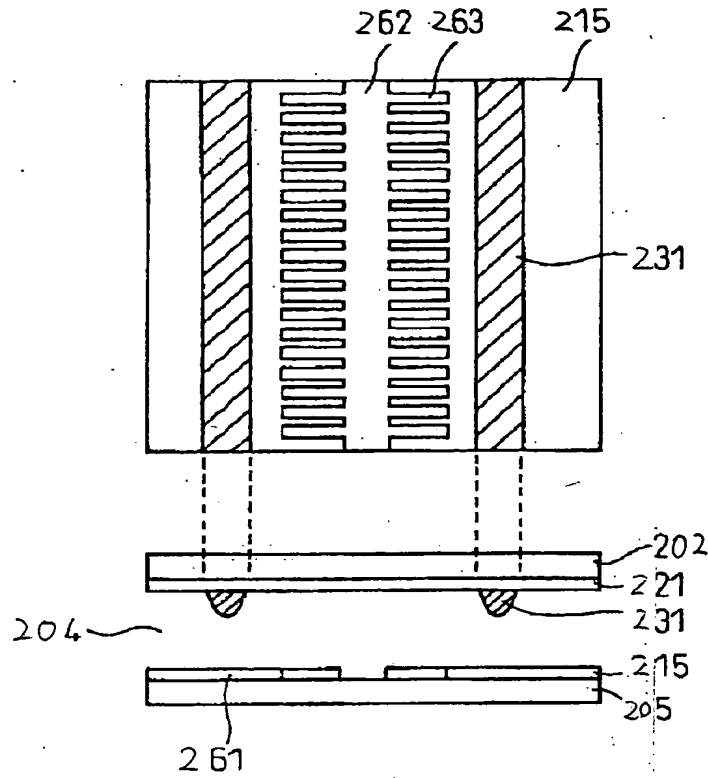


Fig. 72

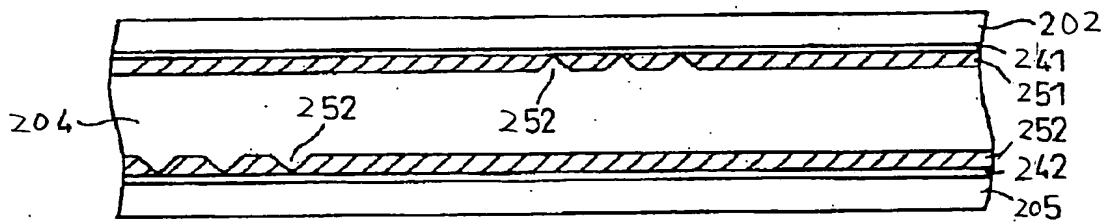


Fig. 73